ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number:	MCP3008T-E/SL
Manufacturer:	Microchip Technology
Package:	16-SOIC (0.154", 3.90mm Width)
Availability:	Please confirm with sales

Product Page:

https://antrexco.com/product/details/microchip-technology/mcp3008t-e-sl.html

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CoC / RoHS / REACH documents available on request

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Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

MCP3004/3008

2.7V 4-Channel/8-Channel 10-Bit A/D Converters with SPI Serial Interface

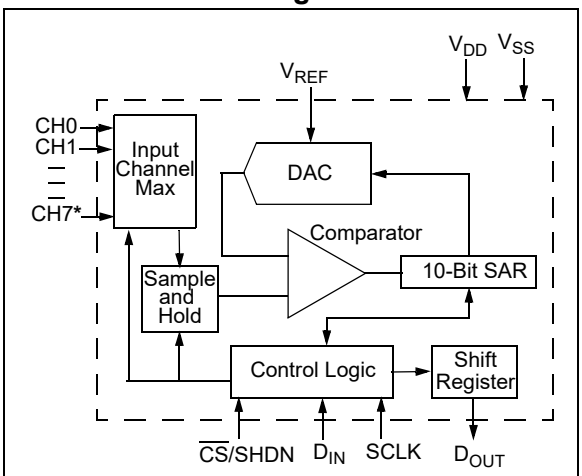
Features

- 10-bit resolution
- ± 1 LSB max DNL
- ± 1 LSB max INL
- 4 (MCP3004) or 8 (MCP3008) input channels
- Analog inputs programmable as single-ended or pseudo-differential pairs
- On-chip sample and hold
- SPI serial interface (modes 0,0 and 1,1)
- Single supply operation: 2.7V - 5.5V
- Sample Rate:
  - 200 ksps max. at V_{DD} = 5V
  - 75 ksps max. at V_{DD} = 2.7V
- Low power CMOS technology
- 5 nA typical standby current, 2 µA max.
- 500 µA max. active current at 5V
- Available in PDIP, SOIC and TSSOP packages
- SOIC-14, SOIC-16, TSSOP-14: AEC-Q100 qualified for automotive applications
  - Temperature Grade 1: -40°C to +125°C
- PDIP-14 and PDIP-16: -40°C to +85°C

Applications

- Sensor Interface, Process Control
- Data Acquisition, Battery Operated Systems

Functional Block Diagram



* **Note:** Channels 4-7 are available on MCP3008 Only

Description

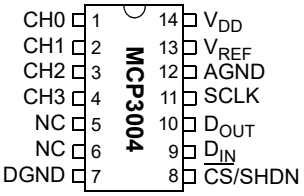
The Microchip Technology Inc. MCP3004/3008 devices are successive approximation 10-bit Analog-to-Digital (A/D) converters with on-board sample and hold circuitry. The MCP3004 is programmable to provide two pseudo-differential input pairs or four single-ended inputs. The MCP3008 is programmable to provide four pseudo-differential input pairs or eight single-ended inputs. Differential Nonlinearity (DNL) and Integral Nonlinearity (INL) are specified at ±1 LSB. Communication with the devices is accomplished using a simple serial interface compatible with the SPI protocol. The devices are capable of conversion rates of up to 200 ksps. The MCP3004/3008 devices operate over a broad voltage range (2.7V - 5.5V). Low-current design permits operation with typical standby currents of only 5 nA and typical active currents of about 300 µA.

The MCP3004 is offered in 14-pin PDIP, 150 mil SOIC and TSSOP packages, while the MCP3008 is offered in 16-pin PDIP and SOIC packages.

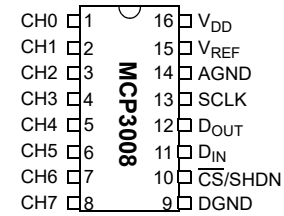
The SOIC and TSSOP packages are AEC-Q100 qualified for automotive applications and operate over the extended temperature range of -40°C to +125°C. The PDIP packages are available for industrial temperature grading (-40°C to +85°C).

Package Types

SOIC-14, TSSOP-14, PDIP-14



SOIC-16, PDIP-16



Note: SOIC and TSSOP packages: -40°C to +125°C
PDIP packages: -40°C to +85°C

NOTES:

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V_{DD} 7.0V
All Inputs and Outputs w.r.t. V_{SS} ..... - 0.6V to V_{DD} + 0.6V
Storage Temperature .....-65°C to +150°C
Ambient temperature with power applied.....-65°C to +150°C
Soldering temperature of leads (10 seconds) ..... +300°C
ESD protection on all pins
CDM: ≤ 2kV at -40°C to +125°C
HBM: ≤ 4kV at -40°C to +125°C

†

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Electrical Characteristics: Unless otherwise noted, all parameters apply at V_{DD} = 5V, V_{REF} = 5V, T_A = -40°C to +125°C, f_{SAMPLE} = 200 ksps and f_{SCLK} = 18*f_{SAMPLE} = 3.6 MHz. Unless otherwise noted, typical values apply for V_{DD} = 5V and T_A = +25°C.

Parameter	Sym	Min	Typ	Max	Units	Conditions
Conversion Rate						
Conversion Time	t_{CONV}	—	—	10	clock cycles	
Analog Input Sample Time	t_{SAMPLE}	—	1.5	—	clock cycles	
Throughput Rate	f_{SAMPLE}	— — —	— — —	200 130 75	ksps ksps ksps	V_{DD} = V_{REF} = 5V V_{DD} = V_{REF} = 3.3V (**Note 1**) V_{DD} = V_{REF} = 2.7V
DC Accuracy						
Resolution		—	10	—	bits	
Integral Nonlinearity	INL	—	±0.5	±1	LSB	
Differential Nonlinearity	DNL	—	±0.25	± 1	LSB	No missing codes over temperature
Offset Error	OS_{ER}	—	0.87	±1.5	LSB	-40°C to +85°C (**Note 4**)
		—	0.87	±1.95	LSB	-40°C to +125°C (**Note 5**)
Gain Error	G_{ER}	—	0.06	±1.0	LSB	
Dynamic Performance						
Total Harmonic Distortion	THD	—	-76	—	dB	V_{IN} = 0.1V to 4.9V@1 kHz
Signal-to-Noise and Distortion	SINAD	—	61	—	dB	V_{IN} = 0.1V to 4.9V@1 kHz
Spurious Free Dynamic Range	SFDR	—	78	—	dB	V_{IN} = 0.1V to 4.9V@1 kHz
Reference Input						
Voltage Range		0.25	—	V_{DD}	V	**Note 2**
Current Drain		— —	100 0.001	150 3	µA µA	During operation Idle state, $\overline{CS}$ = V_{DD} = 5V

Note 1: This parameter is established by characterization and not 100% tested.
2: See graphs that relate linearity performance to V_{REF} levels.
3: Because the sample cap will eventually lose charge, effective clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures. See **Section 6.2 "Maintaining Minimum Clock Speed"**, "Maintaining Minimum Clock Speed", for more information.
4: This parameter specification applies to industrial temperature grading device option (-40°C to +85°C).
5: This parameter specification applies to automotive grade 1 device option (-40°C to +125°C).

Electrical Characteristics: Unless otherwise noted, all parameters apply at V_{DD} = 5V, V_{REF} = 5V, T_A = -40°C to +125°C, f_{SAMPLE} = 200 ksps and f_{SCLK} = 18*f_{SAMPLE} = 3.6 MHz. Unless otherwise noted, typical values apply for V_{DD} = 5V and T_A = +25°C.

Parameter	Sym	Min	Typ	Max	Units	Conditions
Analog Inputs						
Input Voltage Range for CH0 or CH1 in Single-Ended Mode	V_{IN}	V_{SS}	—	V_{REF}	V	
Input Voltage Range for IN+ in pseudo-differential mode		IN-	—	V_{REF} + IN-	V	
Input Voltage Range for IN- in pseudo-differential mode		V_{SS} - 100	—	V_{SS} + 100	mV	
Leakage Current		—	0.001	±1	µA	
Switch Resistance		—	1000	—	Ω	See **Figure 4-1**
Sample Capacitor		—	20	—	pF	See **Figure 4-1**
Digital Input/Output						
Data Coding Format		Straight Binary				
High Level Input Voltage	V_{IH}	0.7 V_{DD}	—	—	V	
Low Level Input Voltage	V_{IL}		—	0.3 V_{DD}	V	
High Level Output Voltage	V_{OH}	4.1	—	—	V	I_{OH} = -1 mA, V_{DD} = 4.5V
Low Level Output Voltage	V_{OL}	—	—	0.4	V	I_{OL} = 1 mA, V_{DD} = 4.5V
Input Leakage Current	I_{LI}	-10	—	10	µA	V_{IN} = V_{SS} or V_{DD}
Output Leakage Current	I_{LO}	-10	—	10	µA	V_{OUT} = V_{SS} or V_{DD}
Pin Capacitance (All Inputs/Outputs)	C_{IN}, C_{OUT}	—	—	10	pF	V_{DD} = 5.0V (**Note 1**) T_A = 25°C, f = 1 MHz
Timing Parameters						
Clock Frequency	f_{SCLK}	—	—	3.6 1.35	MHz MHz	V_{DD} = 5V (**Note 3**) V_{DD} = 2.7V (**Note 3**)
Clock High Time	t_{HI}	125	—	—	ns	
Clock Low Time	t_{LO}	125	—	—	ns	
$\overline{CS}$ Fall To First Rising SCLK Edge	t_{SUCS}	100	—	—	ns	
$\overline{CS}$ Fall To Falling SCLK Edge	t_{CSD}	—	—	0	ns	
Data Input Setup Time	t_{SU}	50	—	—	ns	
Data Input Hold Time	t_{HD}	50	—	—	ns	
SCLK Fall To Output Data Valid	t_{DO}	—	—	125 200	ns ns	V_{DD} = 5V, See **Figure 1-2** V_{DD} = 2.7V, See **Figure 1-2**
SCLK Fall To Output Enable	t_{EN}	—	—	125 200	ns ns	V_{DD} = 5V, See **Figure 1-2** V_{DD} = 2.7V, See **Figure 1-2**
$\overline{CS}$ Rise To Output Disable	t_{DIS}	—	—	100	ns	See Test Circuits, **Figure 1-2**
$\overline{CS}$ Disable Time	t_{CSH}	270	—	—	ns	
D_{OUT} Rise Time	t_R	—	—	100	ns	See Test Circuits, **Figure 1-2** (**Note 1**)
D_{OUT} Fall Time	t_F	—	—	100	ns	See Test Circuits, **Figure 1-2** (**Note 1**)

Note 1: This parameter is established by characterization and not 100% tested.

2: See graphs that relate linearity performance to V_{REF} levels.

3: Because the sample cap will eventually lose charge, effective clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures. See **Section 6.2 "Maintaining Minimum Clock Speed"**, "Maintaining Minimum Clock Speed", for more information.

4: This parameter specification applies to industrial temperature grading device option (-40°C to +85°C).

5: This parameter specification applies to automotive grade 1 device option (-40°C to +125°C).

Electrical Characteristics: Unless otherwise noted, all parameters apply at V_{DD} = 5V, V_{REF} = 5V, T_A = -40°C to +125°C, f_{SAMPLE} = 200 ksps and f_{SCLK} = 18*f_{SAMPLE} = 3.6 MHz. Unless otherwise noted, typical values apply for V_{DD} = 5V and T_A = +25°C.						
Parameter	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Power Requirements						
Operating Voltage	V_{DD}	2.7	—	5.5	V	
Operating Current	I_{DD}	—	425	550	µA	V_{DD} = V_{REF} = 5V
		—	287	—		V_{DD} = V_{REF} = 3.3V, f_{SAMPLE} = 130 kSPS
		—	216	—		V_{DD} = V_{REF} = 2.7V f_{SAMPLE} = 75 kSPS D_{OUT} unloaded for all cases
Standby Current	I_{DDS}	—	0.005	2	µA	$\overline{CS}$ = V_{DD} = 5.0V

Note 1: This parameter is established by characterization and not 100% tested.

2: See graphs that relate linearity performance to V_{REF} levels.

3: Because the sample cap will eventually lose charge, effective clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures. See **Section 6.2 "Maintaining Minimum Clock Speed"**, "Maintaining Minimum Clock Speed", for more information.

4: This parameter specification applies to industrial temperature grading device option (-40°C to +85°C).

5: This parameter specification applies to automotive grade 1 device option (-40°C to +125°C).

TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated, V_{DD} = +2.7V to +5.5V, V_{SS} = GND.						
Parameters	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Temperature Ranges						
Specified Temperature Range	T_A	-40	—	+85	°C	
Operating Temperature Range	T_A	-40	—	+85	°C	
Storage Temperature Range	T_A	-65	—	+150	°C	
Thermal Package Resistances						
Thermal Resistance, 14L-PDIP	θ_{JA}	—	70	—	°C/W	
Thermal Resistance, 14L-SOIC	θ_{JA}	—	108	—	°C/W	
Thermal Resistance, 14L-TSSOP	θ_{JA}	—	100	—	°C/W	
Thermal Resistance, 16L-PDIP	θ_{JA}	—	70	—	°C/W	
Thermal Resistance, 16L-SOIC	θ_{JA}	—	90	—	°C/W	

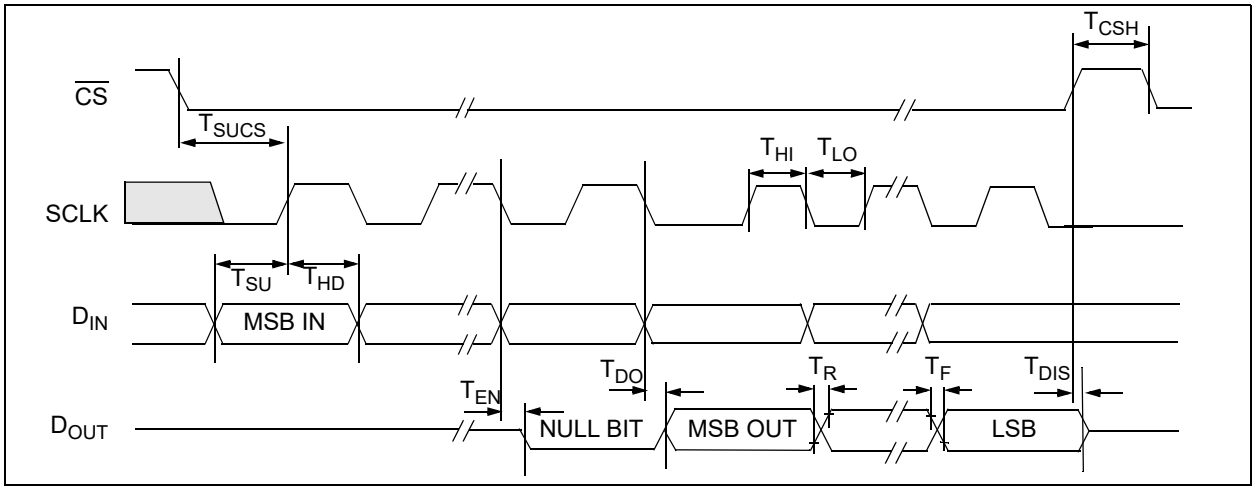


FIGURE 1-1: *Serial Interface Timing.*

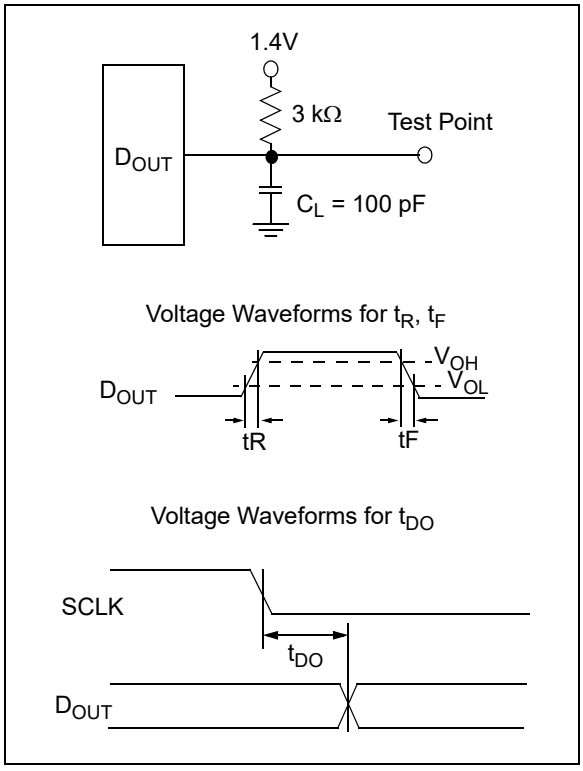


FIGURE 1-2: *Load Circuit for t_R, t_F, t_{DO}.*

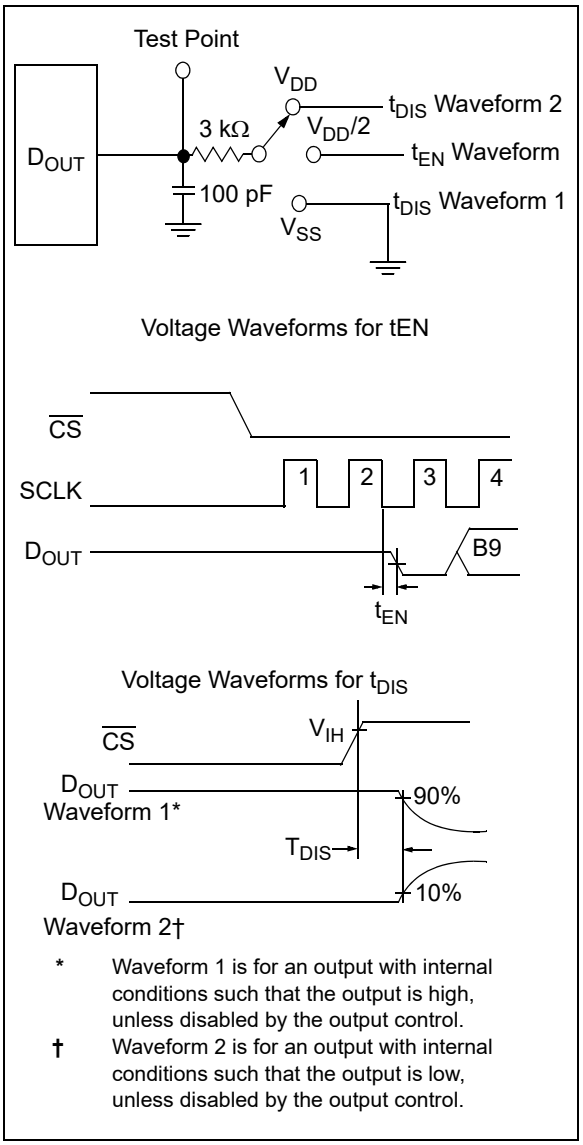


FIGURE 1-3: *Load Circuit for t_{DIS} and t_{EN}.*

2.0 TYPICAL PERFORMANCE CHARACTERISTICS

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18 * f_{SAMPLE}$, $T_A = +25°C$.

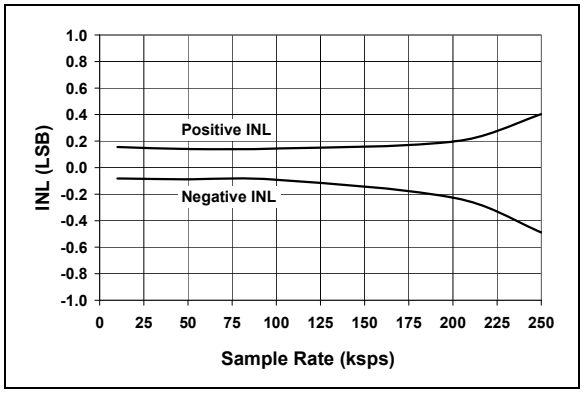


FIGURE 2-1: *Integral Nonlinearity (INL) vs. Sample Rate.*

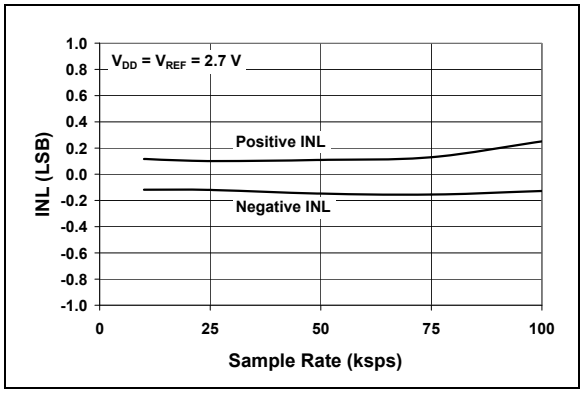


FIGURE 2-4: *Integral Nonlinearity (INL) vs. Sample Rate (V_{DD} = 2.7V).*

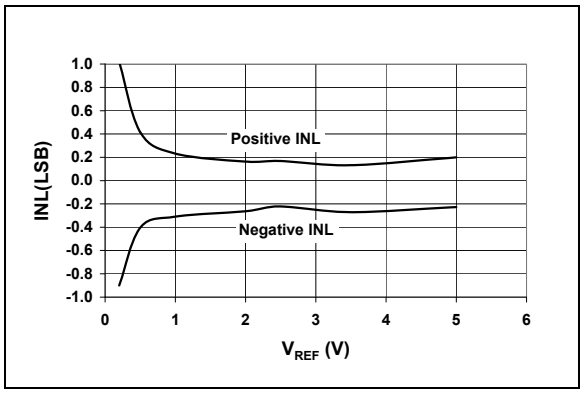


FIGURE 2-2: *Integral Nonlinearity (INL) vs. V_{REF}.*

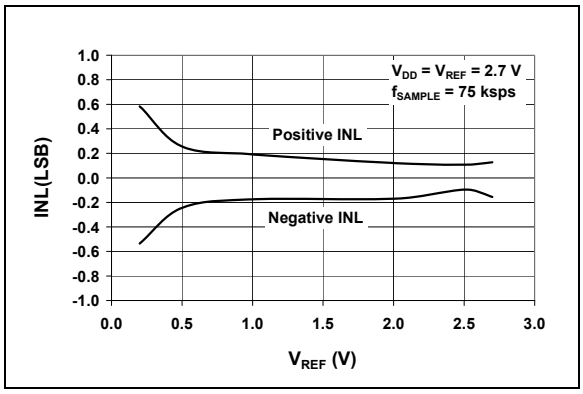


FIGURE 2-5: *Integral Nonlinearity (INL) vs. V_{REF} (V_{DD} = 2.7V).*

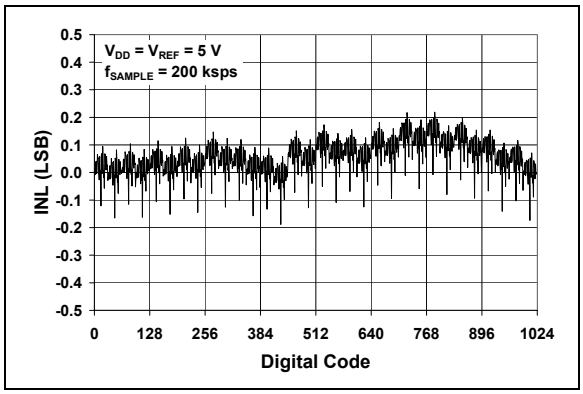


FIGURE 2-3: *Integral Nonlinearity (INL) vs. Code (Representative Part).*

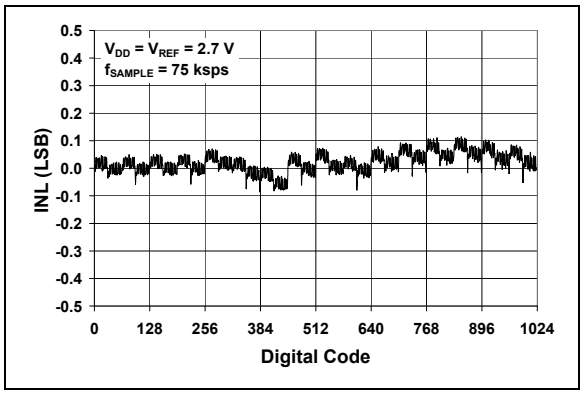


FIGURE 2-6: *Integral Nonlinearity (INL) vs. Code (Representative Part, V_{DD} = 2.7V).*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18^* f_{SAMPLE}$, $T_A = +25°C$.

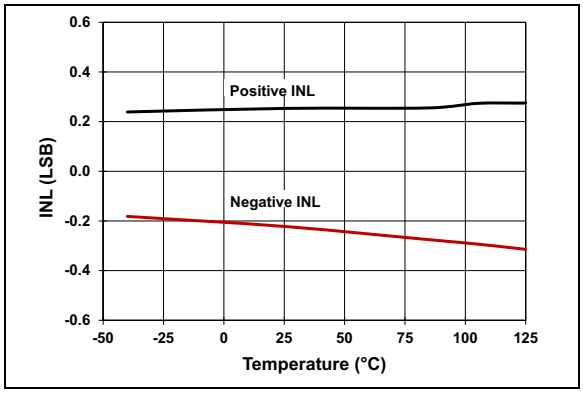


FIGURE 2-7: *Integral Nonlinearity (INL) vs. Temperature.*

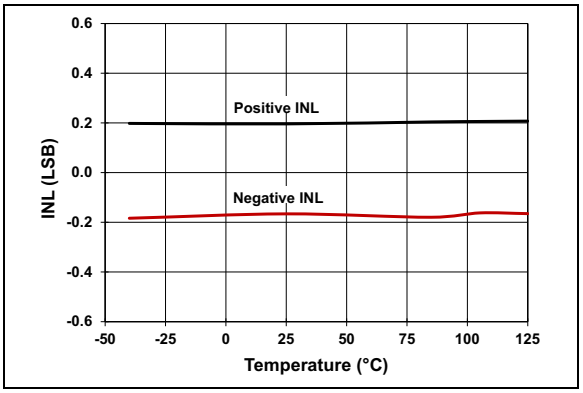


FIGURE 2-10: *Integral Nonlinearity (INL) vs. Temperature (V_{DD} = 2.7V).*

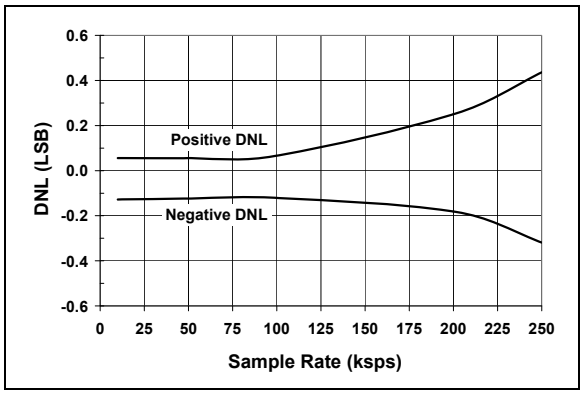


FIGURE 2-8: *Differential Nonlinearity (DNL) vs. Sample Rate.*

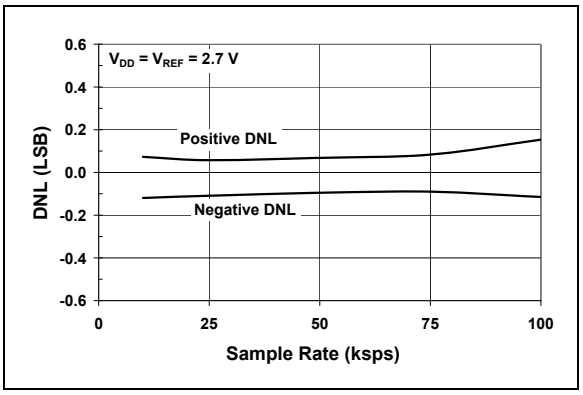


FIGURE 2-11: *Differential Nonlinearity (DNL) vs. Sample Rate (V_{DD} = 2.7V).*

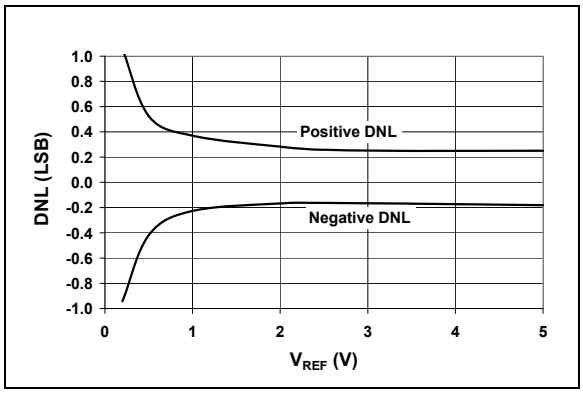


FIGURE 2-9: *Differential Nonlinearity (DNL) vs. V_{REF}.*

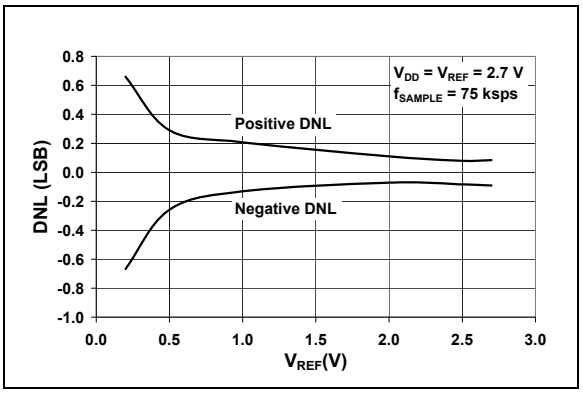


FIGURE 2-12: *Differential Nonlinearity (DNL) vs. V_{REF} (V_{DD} = 2.7V).*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18^* f_{SAMPLE}$, $T_A = +25°C$.

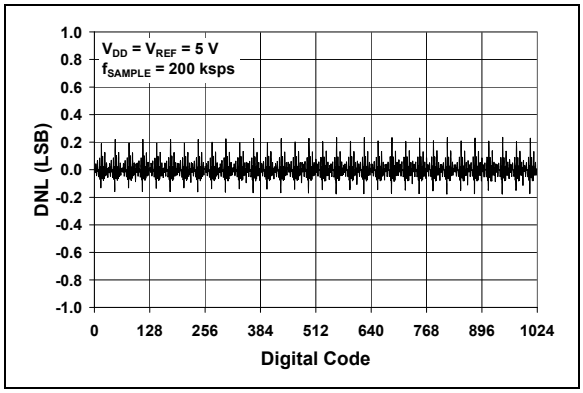


FIGURE 2-13: *Differential Nonlinearity (DNL) vs. Code (Representative Part).*

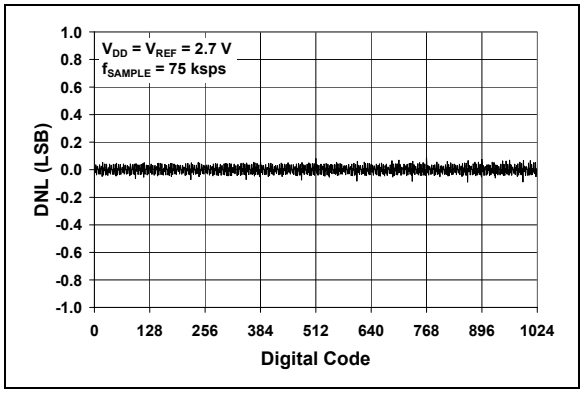


FIGURE 2-16: *Differential Nonlinearity (DNL) vs. Code (Representative Part, V_{DD} =2.7V).*

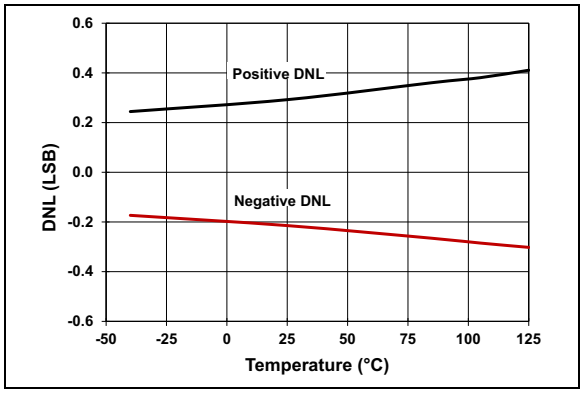


FIGURE 2-14: *Differential Nonlinearity (DNL) vs. Temperature.*

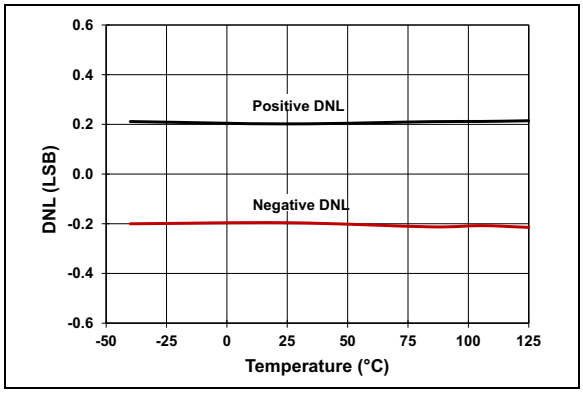


FIGURE 2-17: *Differential Nonlinearity (DNL) vs. Temperature (V_{DD} = 2.7V).*

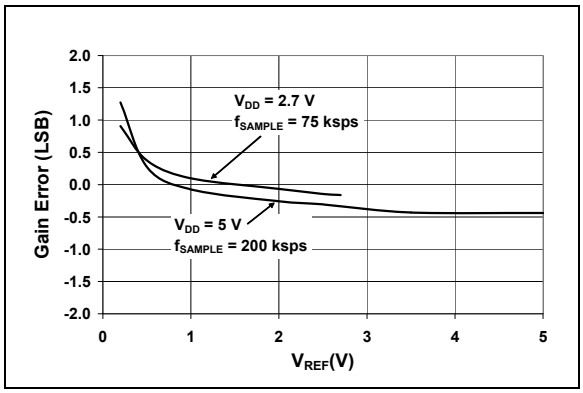


FIGURE 2-15: *Gain Error vs. V_{REF}.*

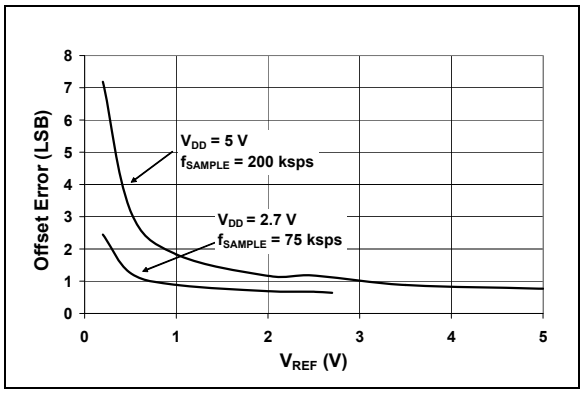


FIGURE 2-18: *Offset Error vs. V_{REF}.*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18 * f_{SAMPLE}$, $T_A = +25°C$.

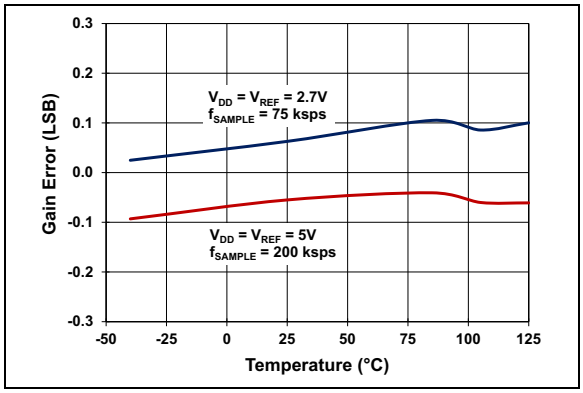


FIGURE 2-19: *Gain Error vs. Temperature.*

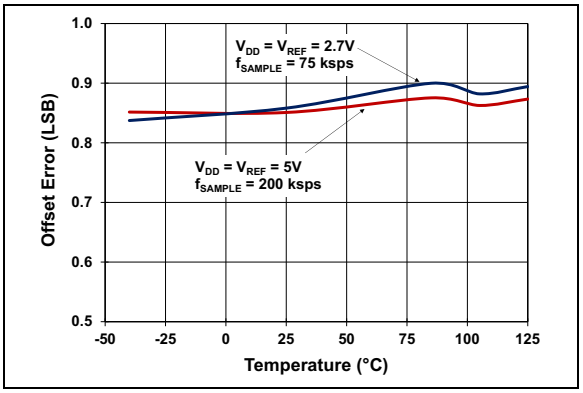


FIGURE 2-22: *Offset Error vs. Temperature.*

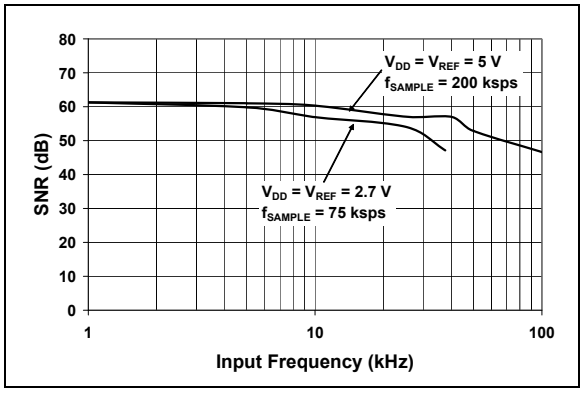


FIGURE 2-20: *Signal-to-Noise (SNR) vs. Input Frequency.*

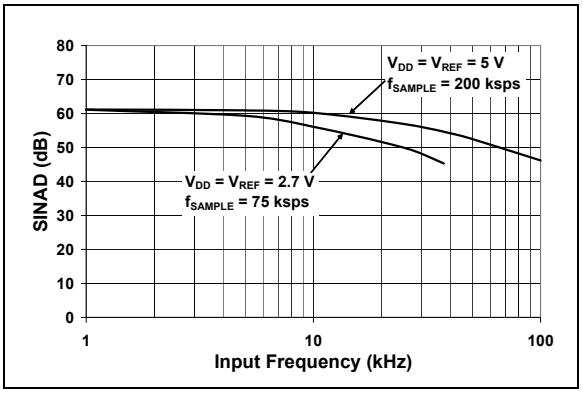


FIGURE 2-23: *Signal-to-Noise and Distortion (SINAD) vs. Input Frequency.*

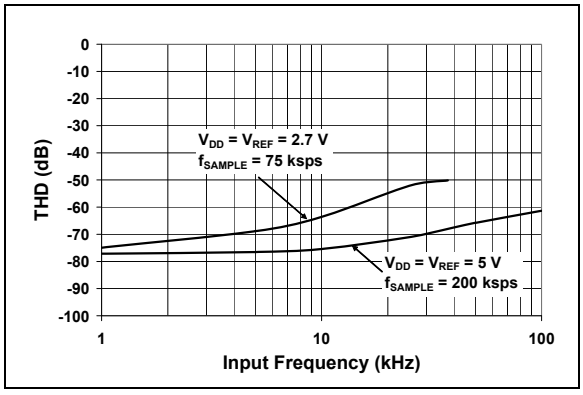


FIGURE 2-21: *Total Harmonic Distortion (THD) vs. Input Frequency.*

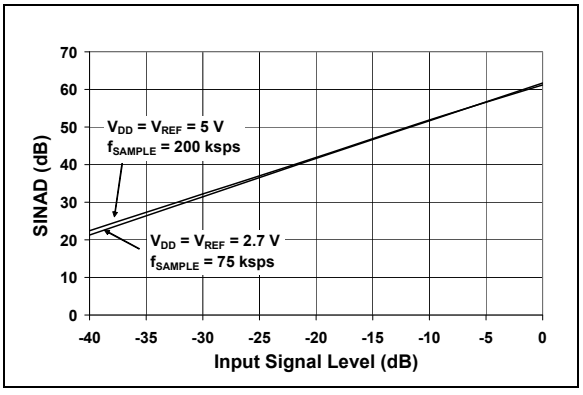


FIGURE 2-24: *Signal-to-Noise and Distortion (SINAD) vs. Input Signal Level.*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18^* f_{SAMPLE}$, $T_A = +25°C$.

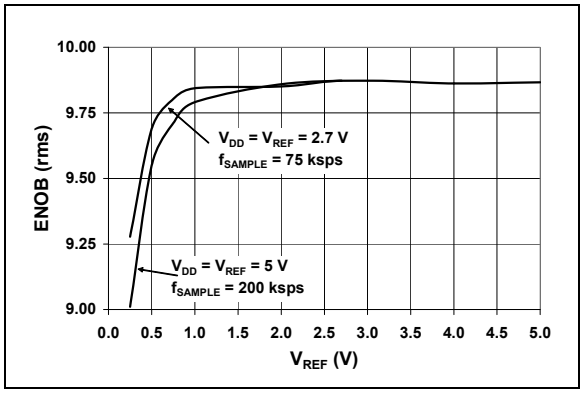


FIGURE 2-25: *Effective Number of Bits (ENOB) vs. V_{REF}.*

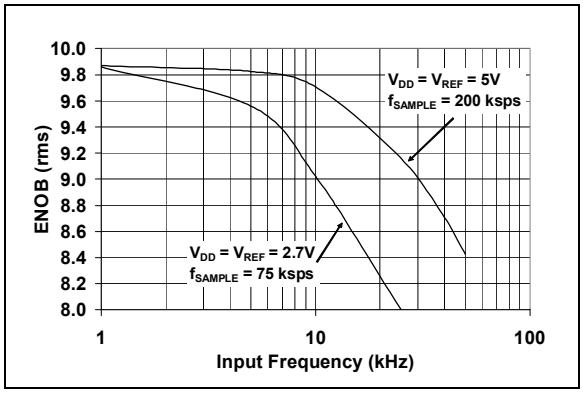


FIGURE 2-28: *Effective Number of Bits (ENOB) vs. Input Frequency.*

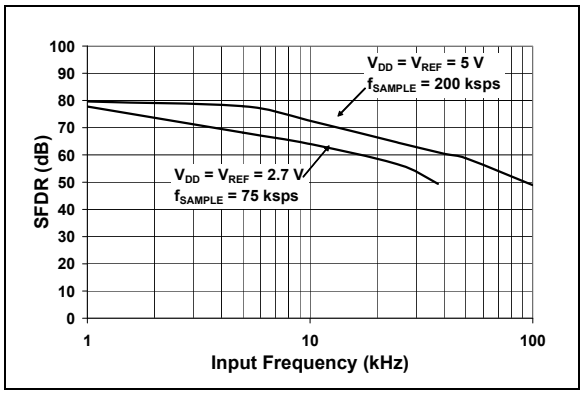


FIGURE 2-26: *Spurious Free Dynamic Range (SFDR) vs. Input Frequency.*

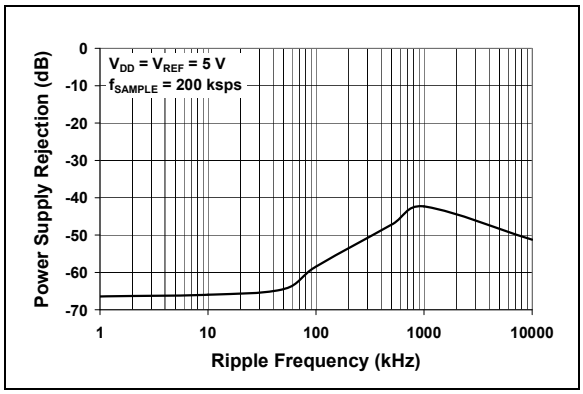


FIGURE 2-29: *Power Supply Rejection (PSR) vs. Ripple Frequency.*

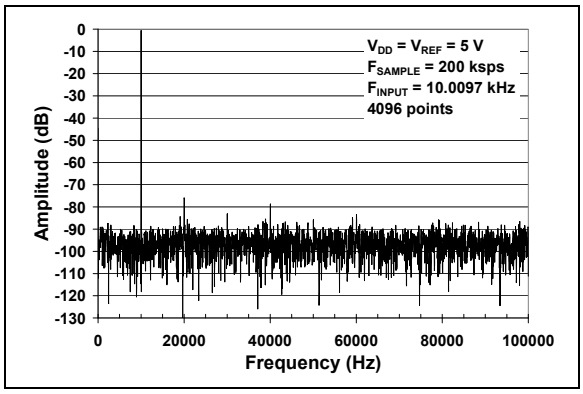


FIGURE 2-27: *Frequency Spectrum of 10 kHz Input (Representative Part).*

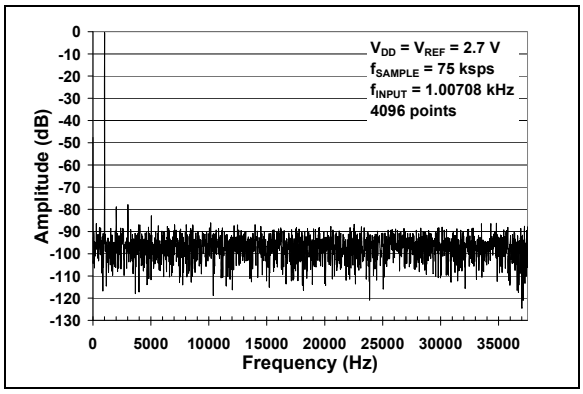


FIGURE 2-30: *Frequency Spectrum of 1 kHz Input (Representative Part, $V_{DD} = 2.7V$).*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18^* f_{SAMPLE}$, $T_A = +25°C$.

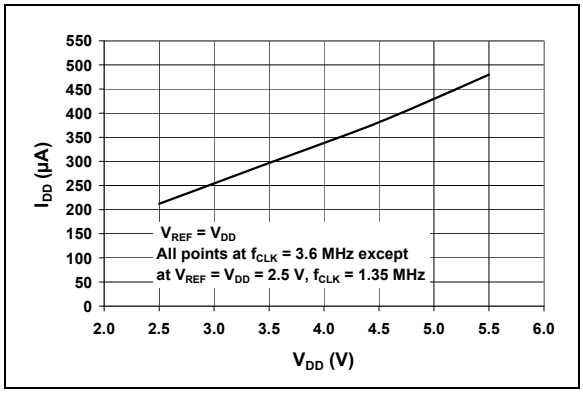


FIGURE 2-31: *I_{DD} vs. V_{DD}.*

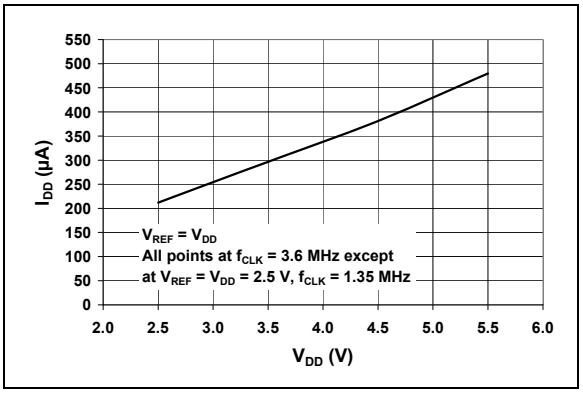


FIGURE 2-34: *I_{REF} vs. V_{DD}.*

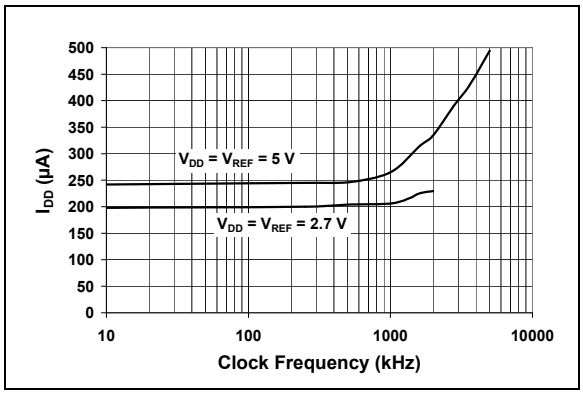


FIGURE 2-32: *I_{DD} vs. Clock Frequency.*

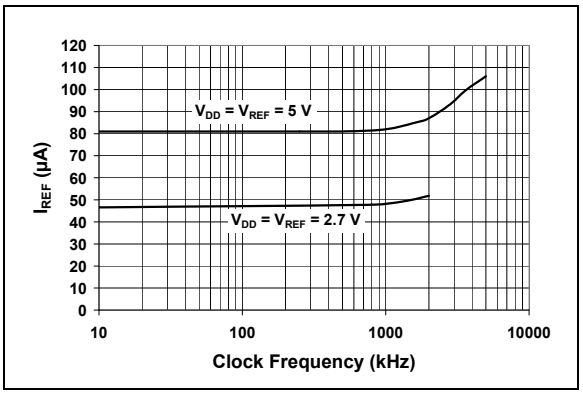


FIGURE 2-35: *I_{REF} vs. Clock Frequency.*

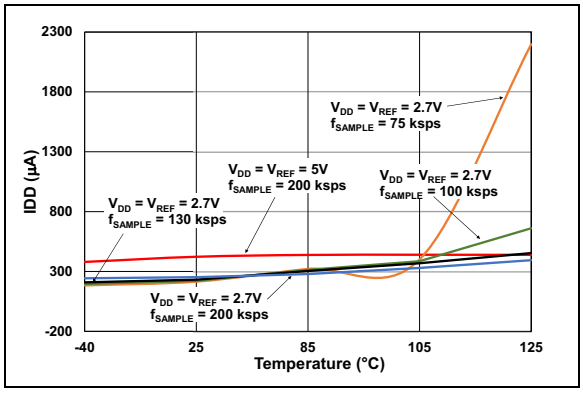


FIGURE 2-33: *I_{DD} vs. Temperature.*

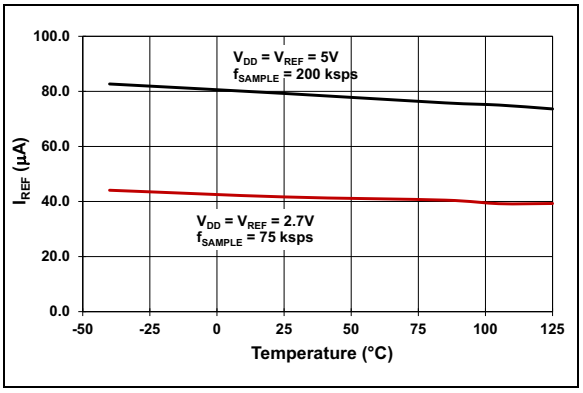


FIGURE 2-36: *I_{REF} vs. Temperature.*

Note: Unless otherwise indicated, $V_{DD} = V_{REF} = 5V$, $f_{SCLK} = 18^* f_{SAMPLE}$, $T_A = +25°C$.

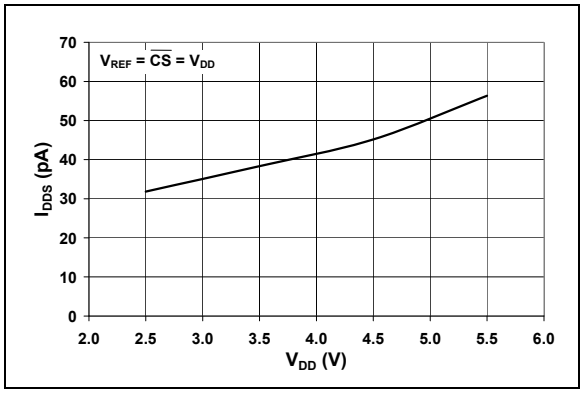


FIGURE 2-37: *I_{DDS} vs. V_{DD}.*

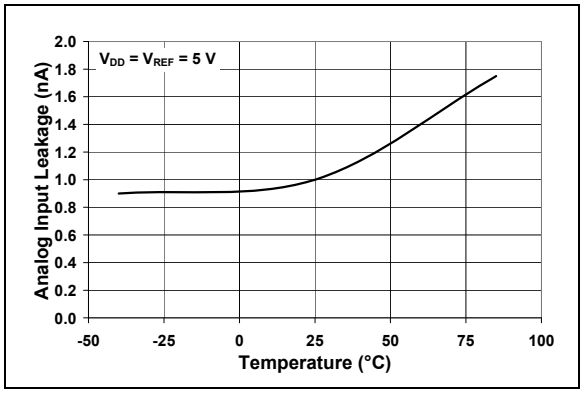


FIGURE 2-39: *Analog Input Leakage Current vs. Temperature.*

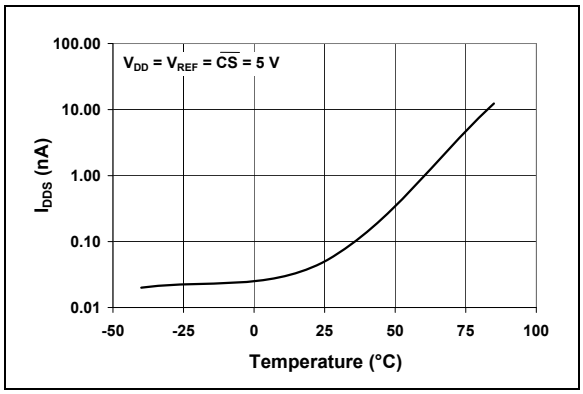


FIGURE 2-38: *I_{DDS} vs. Temperature.*

Note: Additional Information with $V_{DD} = V_{REF} = 3.3V$, $f_{SAMPLE} = 130$ ksps, $f_{SCLK} = 18^* f_{SAMPLE} = 2.34$ MHz.

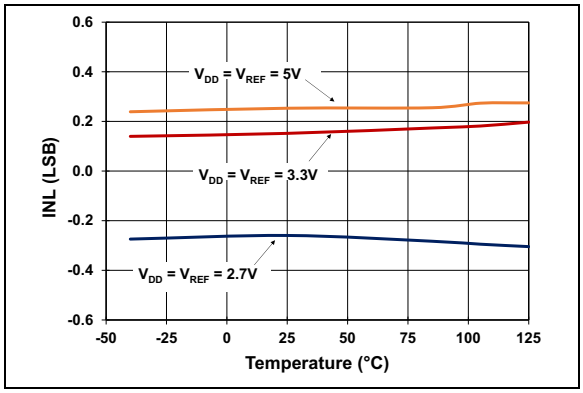


FIGURE 2-40: *Integral Nonlinearity (INL) vs. Temperature (f_{SAMPLE} = 130 ksps).*

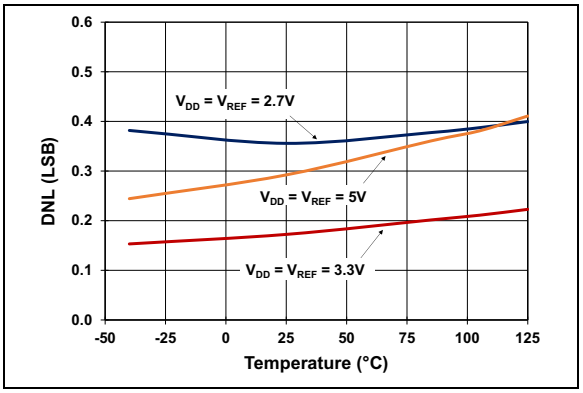


FIGURE 2-42: *Differential Nonlinearity (DNL) vs. Temperature (f_{SAMPLE} = 130 ksps).*

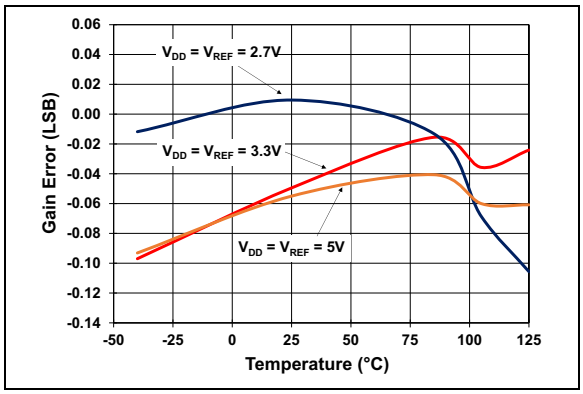


FIGURE 2-41: *Gain Error vs. Temperature.*

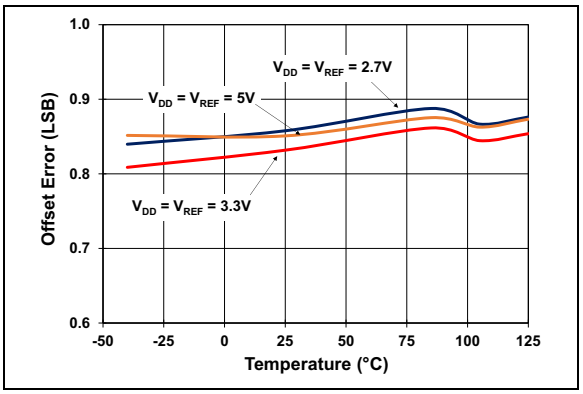


FIGURE 2-43: *Offset Error vs. Temperature.*

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1. Additional descriptions of the device pins follows.

TABLE 3-1: PIN FUNCTION TABLE

MCP3004	MCP3008	Symbol	Description
PDIP, SOIC, TSSOP	PDIP, SOIC		
1	1	CH0	Analog Input
2	2	CH1	Analog Input
3	3	CH2	Analog Input
4	4	CH3	Analog Input
–	5	CH4	Analog Input
–	6	CH5	Analog Input
–	7	CH6	Analog Input
–	8	CH7	Analog Input
7	9	DGND	Digital Ground
8	10	$\overline{CS}$/SHDN	Chip Select/Shutdown Input
9	11	D_{IN}	Serial Data In
10	12	D_{OUT}	Serial Data Out
11	13	SCLK	Serial Clock
12	14	AGND	Analog Ground
13	15	V_{REF}	Reference Voltage Input
14	16	V_{DD}	+2.7V to 5.5V Power Supply
5,6	–	NC	No Connection

3.1 Digital Ground (DGND)

Digital ground connection to internal digital circuitry.

3.2 Analog Ground (AGND)

Analog ground connection to internal analog circuitry.

3.3 Analog inputs (CH0 - CH7)

Analog inputs for channels 0 - 7, respectively, for the multiplexed inputs. Each pair of channels can be programmed to be used as two independent channels in single-ended mode or as a single pseudo-differential input where one channel is IN+ and one channel is IN. See **Section 4.1 "Analog Inputs"**, "Analog Inputs", and **Section 5.0 "Serial Communication"**, "Serial Communication", for information on programming the channel configuration.

3.4 Serial Clock (SCLK)

The SPI clock pin is used to initiate a conversion and clock out each bit of the conversion as it takes place. See **Section 6.2 "Maintaining Minimum Clock Speed"**, "Maintaining Minimum Clock Speed", for constraints on clock speed.

3.5 Serial Data Input (D_{IN})

The SPI port serial data input pin is used to load channel configuration data into the device.

3.6 Serial Data Output (D_{OUT})

The SPI serial data output pin is used to shift out the results of the A/D conversion. Data will always change on the falling edge of each clock as the conversion takes place.

3.7 Chip Select/Shutdown ($\overline{CS}$/SHDN)

The $\overline{CS}$/SHDN pin is used to initiate communication with the device when pulled low. When pulled high, it will end a conversion and put the device in low-power standby. The $\overline{CS}$/SHDN pin must be pulled high between conversions.

NOTES:

4.0 DEVICE OPERATION

The MCP3004/3008 A/D converters employ a conventional SAR architecture. With this architecture, a sample is acquired on an internal sample/hold capacitor for 1.5 clock cycles starting on the first rising edge of the serial clock once $\overline{CS}$ has been pulled low. Following this sample time, the device uses the collected charge on the internal sample and hold capacitor to produce a serial 10-bit digital output code. Conversion rates of 200 ksps are possible on the MCP3004/3008. See **Section 6.2 "Maintaining Minimum Clock Speed"**, "Maintaining Minimum Clock Speed", for information on minimum clock rates. Communication with the device is accomplished using a 4-wire SPI-compatible interface.

4.1 Analog Inputs

The MCP3004/3008 devices offer the choice of using the analog input channels configured as single-ended inputs or pseudo-differential pairs. The MCP3004 can be configured to provide two pseudo-differential input pairs or four single-ended inputs. The MCP3008 can be configured to provide four pseudo-differential input pairs or eight single-ended inputs. Configuration is done as part of the SPI serial communication command before each conversion begins. When used in the pseudo-differential mode, each channel pair (i.e., CH0 and CH1, CH2 and CH3 etc.) are programmed as the IN+ and IN- inputs as part of the command string transmitted to the device. The IN+ input can range from IN- to (V_{REF} + IN-). The IN- input is limited to ±100 mV from the V_{SS} rail. The IN- input can be used to cancel small signal common-mode noise, which is present on both the IN+ and IN- inputs.

When operating in the pseudo-differential mode, if the voltage level of IN+ is equal to or less than IN-, the resultant code will be `000h`. If the voltage at IN+ is equal to or greater than {[V_{REF} + (IN-)] - 1 LSB}, then the output code will be `3FFh`. If the voltage level at IN- is more than 1 LSB below V_{SS}, the voltage level at the IN+ input will have to go below V_{SS} to see the `000h` output code. Conversely, if IN- is more than 1 LSB above V_{SS}, the `3FFh` code will not be seen unless the IN+ input level goes above V_{REF} level.

For the A/D converter to meet specification, the charge holding capacitor (C_{SAMPLE}) must be given enough time to acquire a 10-bit accurate voltage level during the 1.5 clock cycle sampling period. The analog input model is shown in Figure 4-1.

This diagram illustrates that the source impedance (R_{SS}) adds to the internal sampling switch (R_S) impedance, directly affecting the time that is required to charge the capacitor (C_{SAMPLE}). Consequently, larger source impedances increase the offset, gain and integral linearity errors of the conversion (see Figure 4-2).

4.2 Reference Input

For each device in the family, the reference input (V_{REF}) determines the analog input voltage range. As the reference input is reduced, the LSB size is reduced accordingly.

EQUATION 4-1: LSB SIZE CALCULATION

$$LSB\ Size = \frac{V_{REF}}{1024}$$

The theoretical digital output code produced by the A/D converter is a function of the analog input signal and the reference input, as shown below.

EQUATION 4-2: DIGITAL OUTPUT CODE CALCULATION

$$Digital\ Output\ Code = \frac{1024 \times V_{IN}}{V_{REF}}$$

Where:

V_{IN} = analog input voltage

V_{REF} = analog input voltage

When using an external voltage reference device, the system designer should always refer to the manufacturer's recommendations for circuit layout. Any instability in the operation of the reference device will have a direct effect on the operation of the A/D converter.

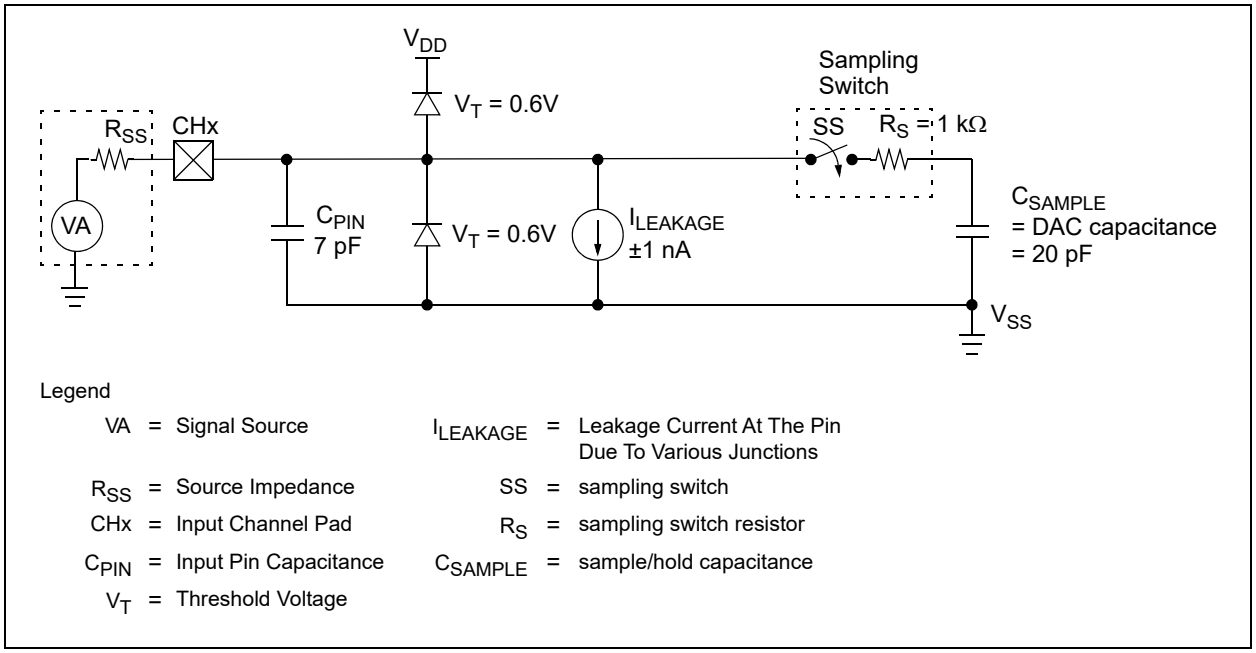


FIGURE 4-1: *Analog Input Model.*

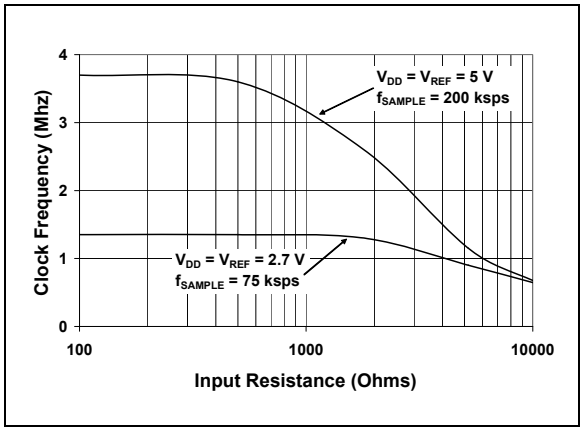


FIGURE 4-2: *Maximum Clock Frequency vs. Input resistance (R_S) to maintain less than a 0.1 LSB deviation in INL from nominal conditions.*

5.0 SERIAL COMMUNICATION

Communication with the MCP3004/3008 devices is accomplished using a standard SPI-compatible serial interface. Initiating communication with either device is done by bringing the $\overline{CS}$ line low (see Figure 5-1). If the device was powered up with the $\overline{CS}$ pin low, it must be brought high and back low to initiate communication. The first clock received with $\overline{CS}$ low and D_{IN} high will constitute a start bit. The SGL/$\overline{DIFF}$ bit follows the start bit and will determine if the conversion will be done using single-ended or differential input mode. The next three bits (D0, D1 and D2) are used to select the input channel configuration. Table 5-1 and Table 5-2 show the configuration bits for the MCP3004 and MCP3008, respectively. The device will begin to sample the analog input on the fourth rising edge of the clock after the start bit has been received. The sample period will end on the falling edge of the fifth clock following the start bit.

Once the D0 bit is input, one more clock is required to complete the sample and hold period (D_{IN} is a "don't care" for this clock). On the falling edge of the next clock, the device will output a low null bit. The next 10 clocks will output the result of the conversion with MSB first, as shown in Figure 5-1. Data is always output from the device on the falling edge of the clock. If all 10 data bits have been transmitted and the device continues to receive clocks while the $\overline{CS}$ is held low, the device will output the conversion result LSB first, as is shown in Figure 5-2. If more clocks are provided to the device while $\overline{CS}$ is still low (after the LSB first data has been transmitted), the device will clock out zeros indefinitely.

If necessary, it is possible to bring $\overline{CS}$ low and clock in leading zeros on the D_{IN} line before the start bit. This is often done when dealing with microcontroller-based SPI ports that must send 8 bits at a time. Refer to **Section 6.1 "Using the MCP3004/3008 with Microcontroller (MCU) SPI Ports"**, "Using the MCP3004/3008 with Microcontroller (MCU) SPI Ports", for more details on using the MCP3004/3008 devices with hardware SPI ports.

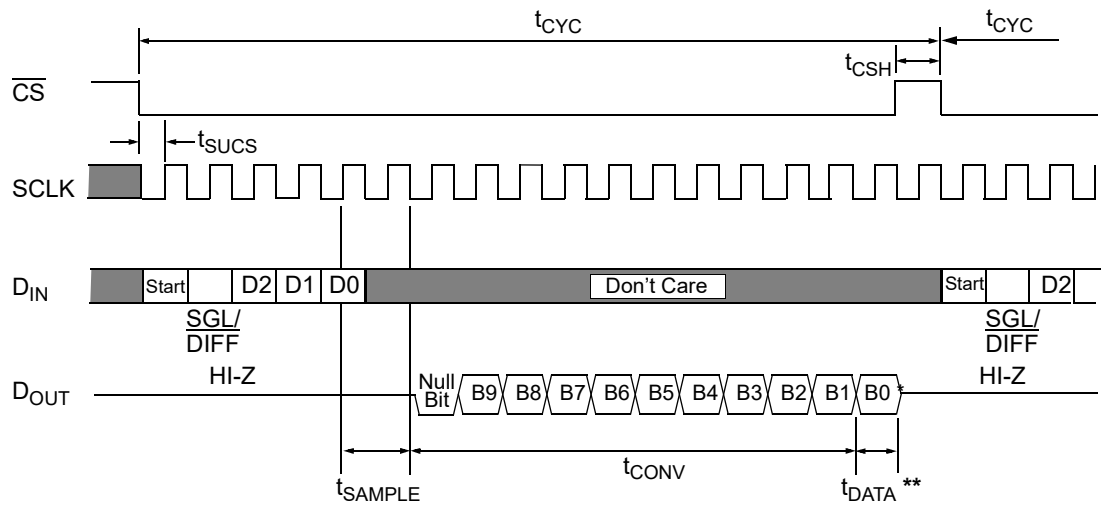
TABLE 5-1: CONFIGURE BITS FOR THE MCP3004

Control Bit Selections				Input Configuration	Channel Selection
Single/$\overline{Diff}$	D2*	D1	D0		
1	X	0	0	single-ended	CH0
1	X	0	1	single-ended	CH1
1	X	1	0	single-ended	CH2
1	X	1	1	single-ended	CH3
0	X	0	0	differential	CH0 = IN+ CH1 = IN-
0	X	0	1	differential	CH0 = IN- CH1 = IN+
0	X	1	0	differential	CH2 = IN+ CH3 = IN-
0	X	1	1	differential	CH2 = IN- CH3 = IN+

* D2 is "don't care" for MCP3004

TABLE 5-2: CONFIGURE BITS FOR THE MCP3008

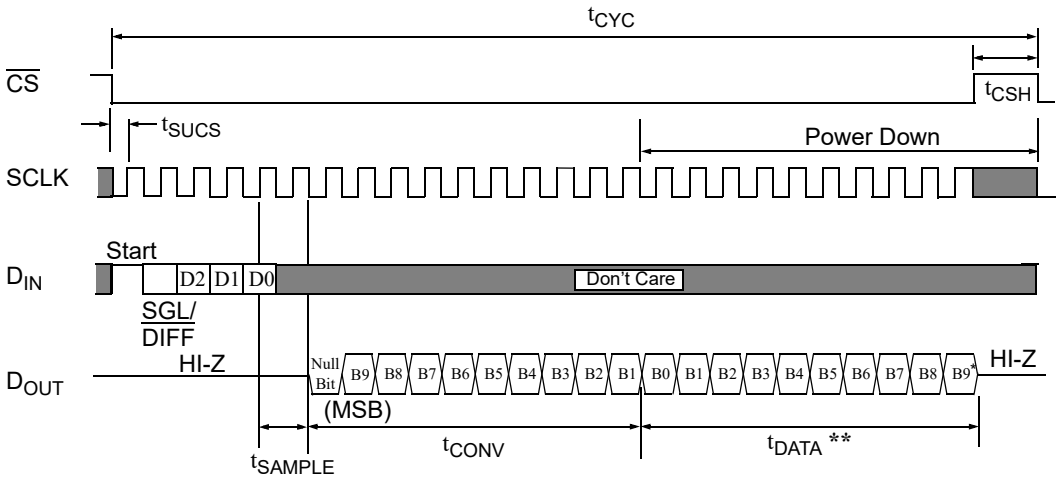
Control Bit Selections				Input Configuration	Channel Selection
Single/$\overline{Diff}$	D2	D1	D0		
1	0	0	0	single-ended	CH0
1	0	0	1	single-ended	CH1
1	0	1	0	single-ended	CH2
1	0	1	1	single-ended	CH3
1	1	0	0	single-ended	CH4
1	1	0	1	single-ended	CH5
1	1	1	0	single-ended	CH6
1	1	1	1	single-ended	CH7
0	0	0	0	differential	CH0 = IN+ CH1 = IN-
0	0	0	1	differential	CH0 = IN- CH1 = IN+
0	0	1	0	differential	CH2 = IN+ CH3 = IN-
0	0	1	1	differential	CH2 = IN- CH3 = IN+
0	1	0	0	differential	CH4 = IN+ CH5 = IN-
0	1	0	1	differential	CH4 = IN- CH5 = IN+
0	1	1	0	differential	CH6 = IN+ CH7 = IN-
0	1	1	1	differential	CH6 = IN- CH7 = IN+



* After completing the data transfer, if further clocks are applied with $\overline{CS}$ low, the A/D converter will output LSB first data, then followed with zeros indefinitely. See Figure 5-2 below.

** t_{DATA}: during this time, the bias current and the comparator powers down while the reference input becomes a high-impedance node.

FIGURE 5-1: *Communication with the MCP3004 or MCP3008.*



* After completing the data transfer, if further clocks are applied with $\overline{CS}$ low, the A/D converter will output zeros indefinitely.

** t_{DATA}: During this time, the bias circuit and the comparator powers down while the reference input becomes a high-impedance node, leaving the SCLK running to clock out LSB first data or zeroes.

FIGURE 5-2: *Communication with MCP3004 or MCP3008 in LSB First Format.*

6.0 APPLICATIONS INFORMATION

6.1 Using the MCP3004/3008 with Microcontroller (MCU) SPI Ports

With most microcontroller SPI ports, it is required to send groups of eight bits. It is also required that the microcontroller SPI port be configured to clock out data on the falling edge of clock and latch data in on the rising edge. Because communication with the MCP3004/3008 devices may not need multiples of eight clocks, it will be necessary to provide more clocks than are required. This is usually done by sending 'leading zeros' before the start bit. As an example, Figure 6-1 and Figure 6-2 shows how the MCP3004/3008 can be interfaced to a MCU with a hardware SPI port. Figure 6-1 depicts the operation shown in SPI Mode 0,0, which requires that the SCLK from the MCU idles in the 'low' state, while Figure 6-2 shows the similar case of SPI Mode 1,1, where the clock idles in the 'high' state.

As is shown in Figure 6-1, the first byte transmitted to the A/D converter contains seven leading zeros before the start bit. Arranging the leading zeros this way induces the 10 data bits to fall in positions easily manipulated by the MCU. The MSB is clocked out of the A/D converter on the falling edge of clock number 14. Once the second eight clocks have been sent to the device, the MCU receive buffer will contain five unknown bits (the output is at high-impedance for the first two clocks), the null bit and the highest order 2 bits of the conversion. Once the third byte has been sent to the device, the receive register will contain the lowest order eight bits of the conversion results. Employing this method ensures simpler manipulation of the converted data.

Figure 6-2 shows the same thing in SPI Mode 1,1, which requires that the clock idles in the high state. As with mode 0,0, the A/D converter outputs data on the falling edge of the clock and the MCU latches data from the A/D converter in on the rising edge of the clock.

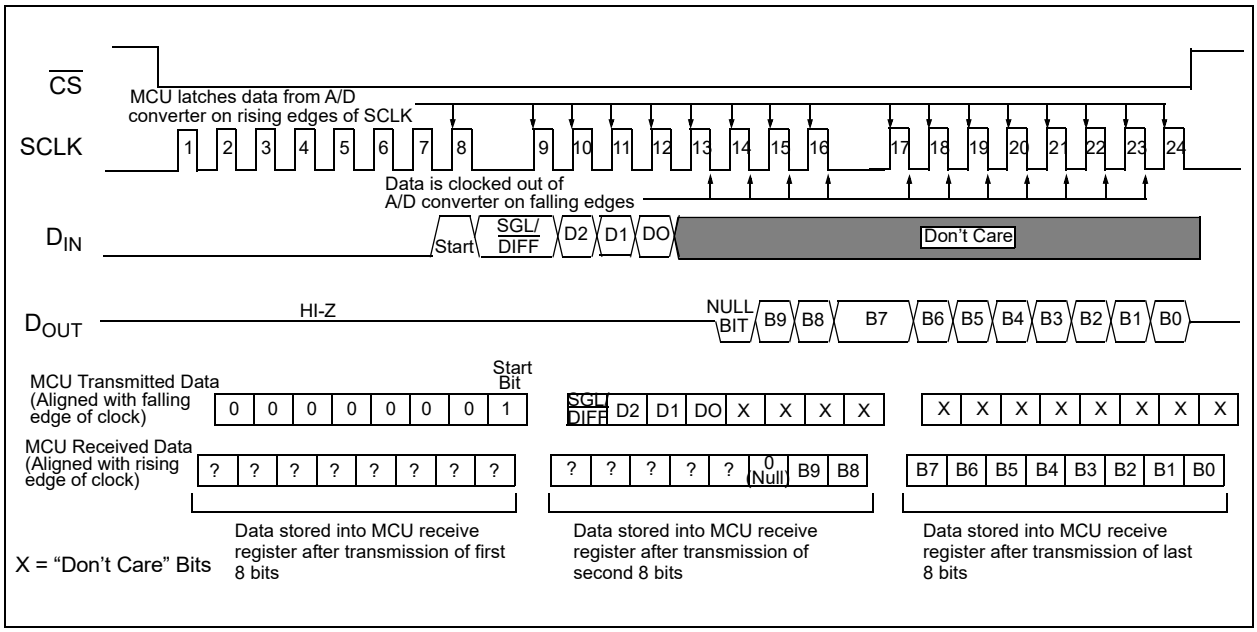


FIGURE 6-1: *SPI Communication with the MCP3004/3008 using 8-bit Segments (Mode 0,0: SCLK idles low).*

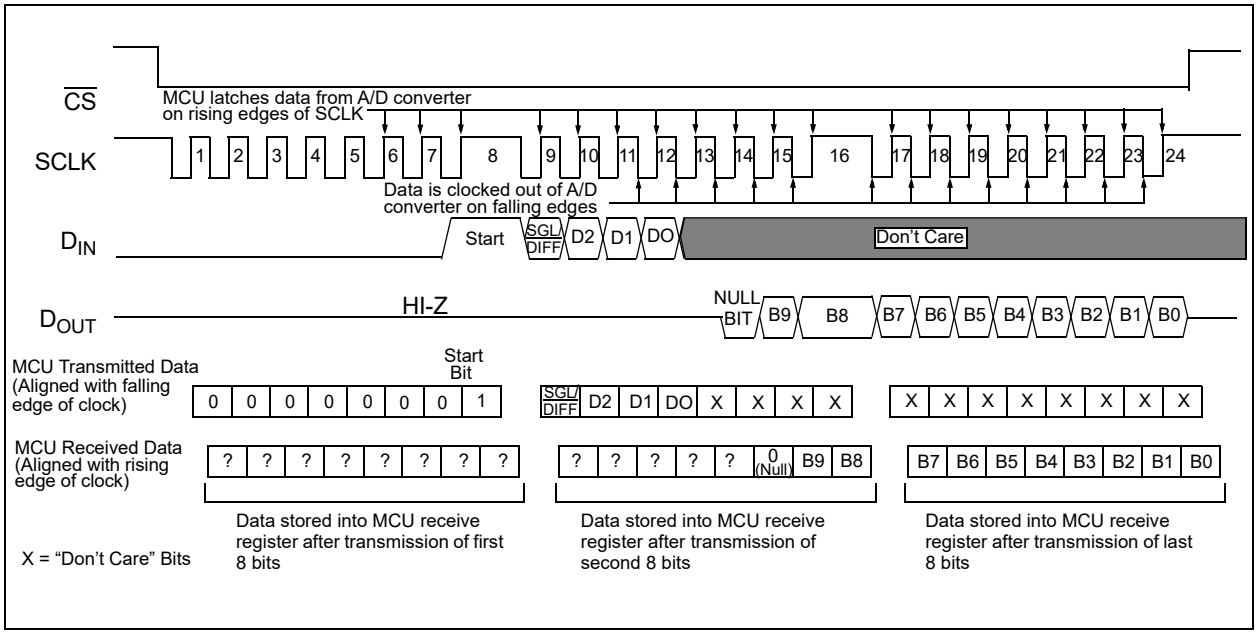


FIGURE 6-2: *SPI Communication with the MCP3004/3008 using 8-bit Segments (Mode 1,1: SCLK idles high).*

6.2 Maintaining Minimum Clock Speed

When the MCP3004/3008 initiates the sample period, charge is stored on the sample capacitor. When the sample period is complete, the device converts one bit for each clock that is received. It is important for the user to note that a slow clock rate will allow charge to bleed off the sample capacitor while the conversion is taking place. At temperatures above +85°C, the part will maintain proper charge on the sample capacitor for at least 1.2 ms after the sample period has ended. This means that the time between the end of the sample period and the time that all 10 data bits have been clocked out must not exceed 1.2 ms (effective clock frequency of 10 kHz). Failure to meet this criterion may introduce linearity errors into the conversion outside the rated specifications. It should be noted that during the entire conversion cycle, the A/D converter does not require a constant clock speed or duty cycle, as long as all timing specifications are met.

6.2.1 SAMPLING RATE VS. SPI CLOCK FREQUENCY

Equation 6-1 shows the relationship between the sampling rate and the SPI clock frequency. Table 6-1 shows the recommended SPI clock frequency.

EQUATION 6-1: SPI CLOCK FREQUENCY VS. SAMPLING RATE

$$f_{SCLK} = 18 \times f_{SAMPLE}$$

TABLE 6-1: SPI CLOCK (SCLK) VS. SAMPLING RATE

Sampling Clock (ksps)	SPI Clock (MHz)
200 (Note 1)	3.6
180	3.24
160	2.88
140	2.52
130 (Note 2)	2.34
120	2.16
100	1.8
80	1.44
75 (Note 3)	1.35

Note 1: 200 ksps is recommended for $V_{DD} \geq 4V$.
2: 130 ksps is recommended for $V_{DD} \geq 3.3V$.
3: 75 ksps is recommended for $V_{DD} = 2.7V$.

6.3 Buffering/Filtering the Analog Inputs

If the signal source for the A/D converter is not a low-impedance source, it will have to be buffered or inaccurate conversion results may occur (see Figure 4-2). It is also recommended that a filter be used to eliminate any signals that may be aliased back in to the conversion results, as is illustrated in Figure 6-3, where an op amp is used to drive, filter and gain the analog input of the MCP3004/3008. This amplifier provides a low-impedance source for the converter input, plus a low-pass filter, which eliminates unwanted high-frequency noise.

Low-pass (anti-aliasing) filters can be designed using Microchip's free interactive FilterLab® software. FilterLab will calculate capacitor and resistors values, as well as determine the number of poles that are required for the application. For more information on filtering signals, see AN699, *"Anti-Aliasing Analog Filters for Data Acquisition Systems"*.

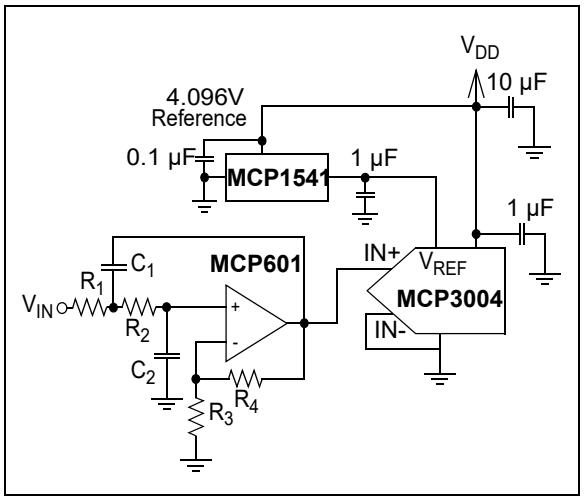


FIGURE 6-3: *The MCP601 Operational Amplifier is used to implement a second order anti-aliasing filter for the signal being converted by the MCP3004.*

6.4 Layout Considerations

When laying out a printed circuit board for use with analog components, care should be taken to reduce noise wherever possible. A bypass capacitor should always be used with this device and should be placed as close as possible to the device pin. A bypass capacitor value of 1 µF is recommended.

Digital and analog traces should be separated as much as possible on the board, with no traces running underneath the device or bypass capacitor. Extra precautions should be taken to keep traces with high-frequency signals (such as clock lines) as far as possible from analog traces.

Use of an analog ground plane is recommended in order to keep the ground potential the same for all devices on the board. Providing V_{DD} connections to devices in a "star" configuration can also reduce noise by eliminating return current paths and associated errors (see Figure 6-4). For more information on layout tips when using A/D converters, refer to AN688, *"Layout Tips for 12-Bit A/D Converter Applications"*.

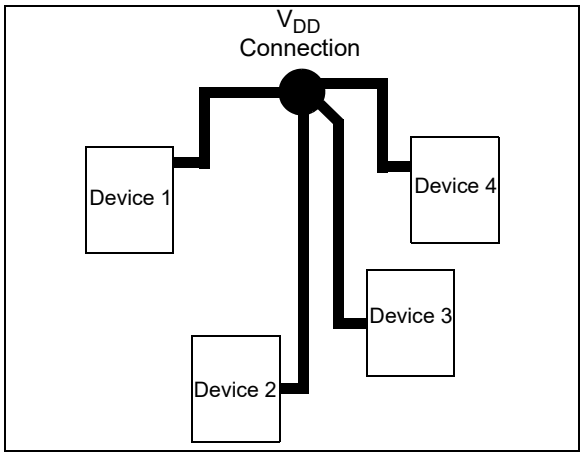


FIGURE 6-4: *V_{DD} traces arranged in a 'Star' configuration in order to reduce errors caused by current return paths.*

6.5 Utilizing the Digital and Analog Ground Pins

The MCP3004/3008 devices provide both digital and analog ground connections to provide additional means of noise reduction. As is shown in Figure 6-5, the analog and digital circuitry is separated internal to the device. This reduces noise from the digital portion of the device being coupled into the analog portion of the device. The two grounds are connected internally through the substrate which has a resistance of 5 -10Ω.

If no ground plane is utilized, both grounds must be connected to V_{SS} on the board. If a ground plane is available, both digital and analog ground pins should be connected to the analog ground plane. If both an analog and a digital ground plane are available, both the digital and the analog ground pins should be connected to the analog ground plane. Following these steps will reduce the amount of digital noise from the rest of the board being coupled into the A/D converter.

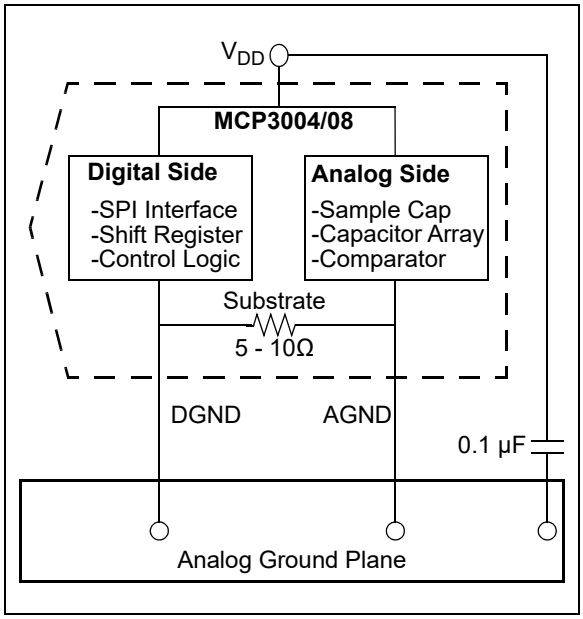
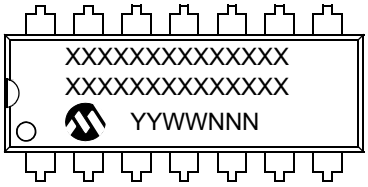


FIGURE 6-5: *Separation of Analog and Digital Ground Pins.*

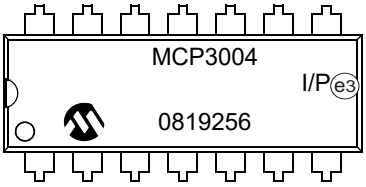
7.0 PACKAGING INFORMATION

7.1 Package Marking Information

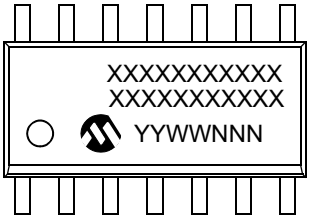
14-Lead PDIP (300 mil)



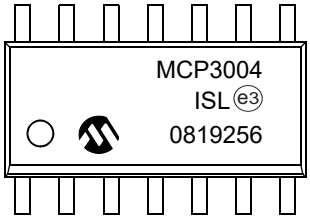
Example:



14-Lead SOIC (150 mil)

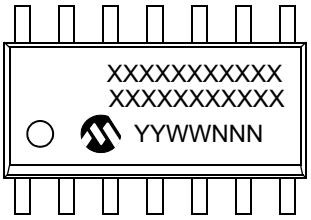


Example:

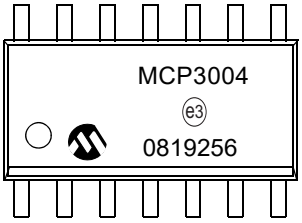


Temperature range:
-40°C to +85°C

14-Lead SOIC (150 mil)

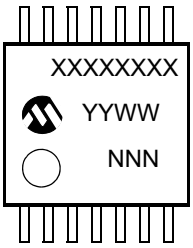


Example:

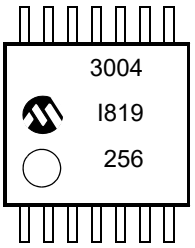


Temperature range:
-40°C to +125°C

14-Lead TSSOP (4.4mm) *



Example:

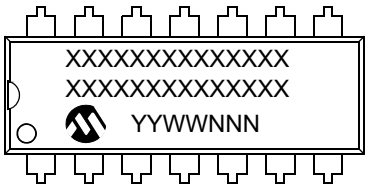


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3) can be found on the outer packaging for this package.

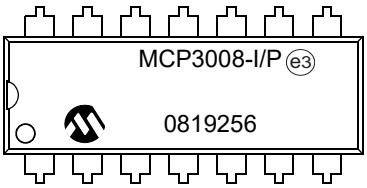
Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

Package Marking Information (Continued)

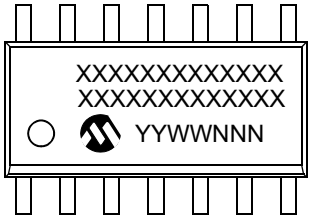
16-Lead PDIP (300 mil) (**MCP3008**)



Example:

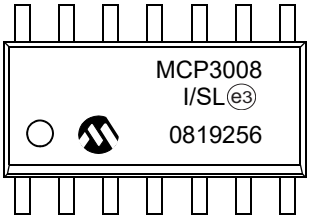


16-Lead SOIC (150 mil) (**MCP3008**)



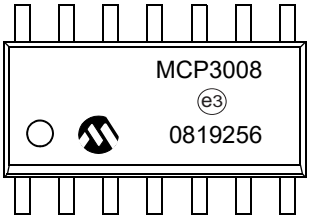
Example:

Temperature range:
-40°C to +85°C



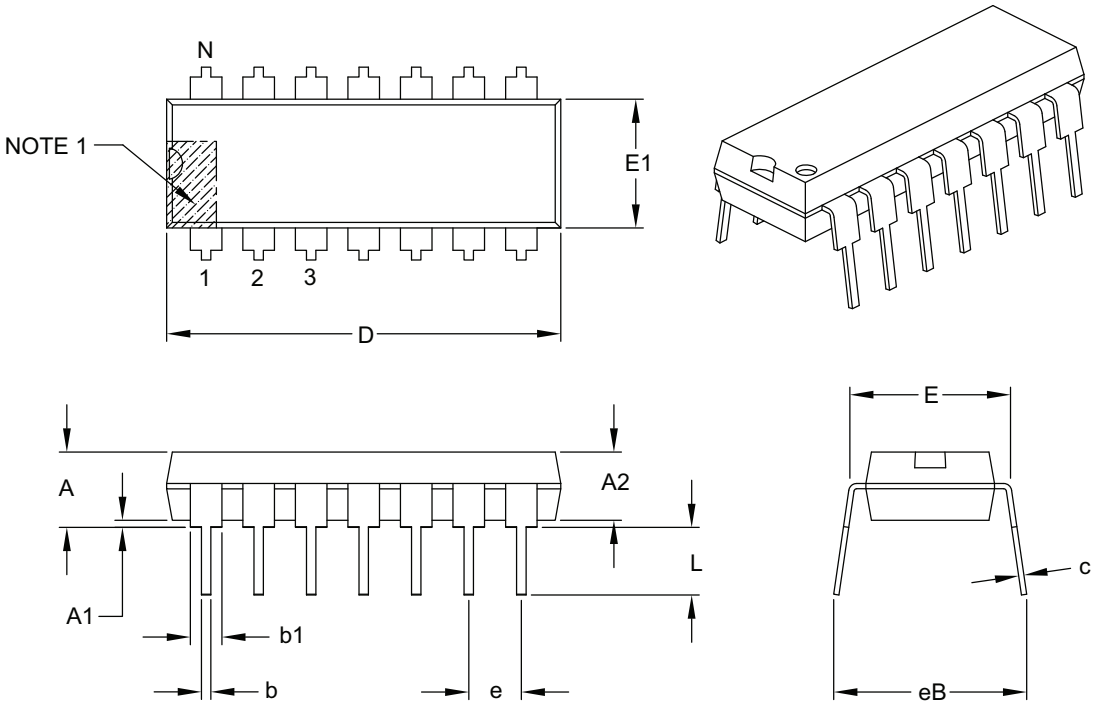
Example:

Temperature range:
-40°C to +125°C



14-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

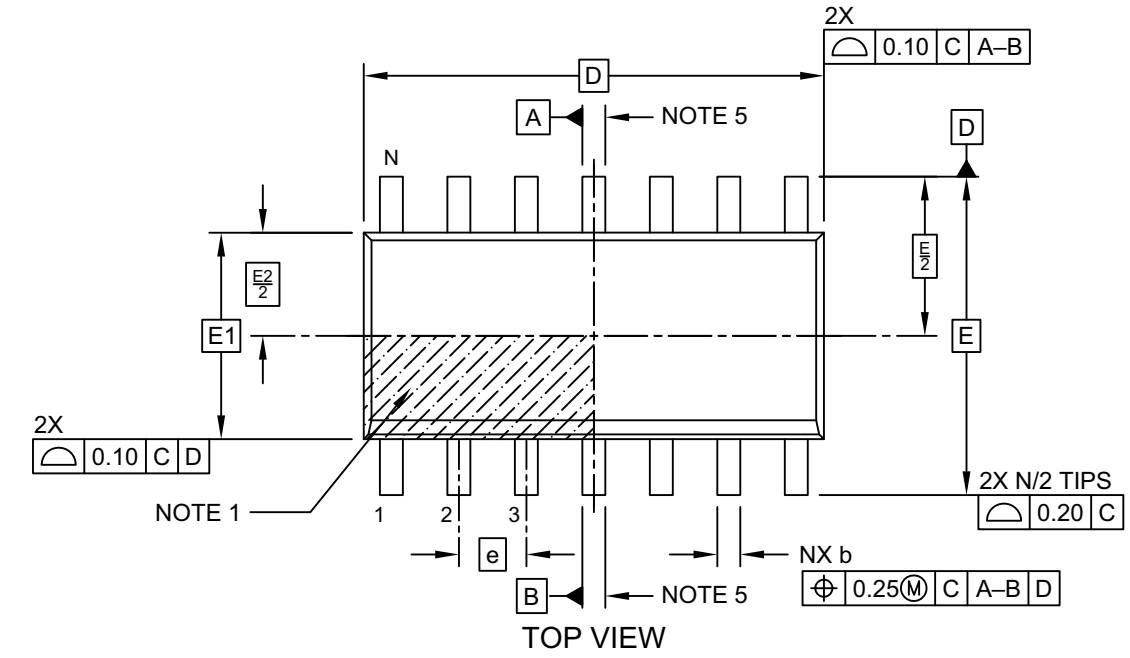
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

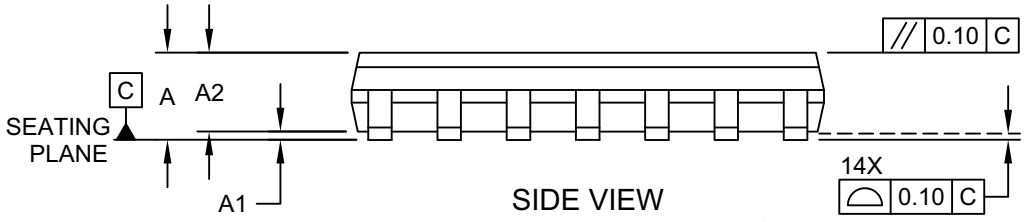
Microchip Technology Drawing C04-005B

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

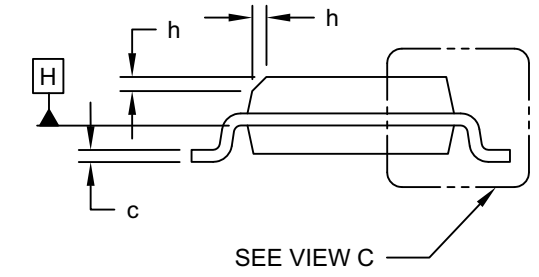
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



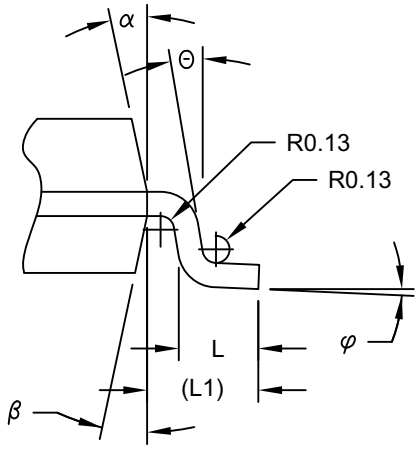
TOP VIEW



SIDE VIEW



VIEW A–A

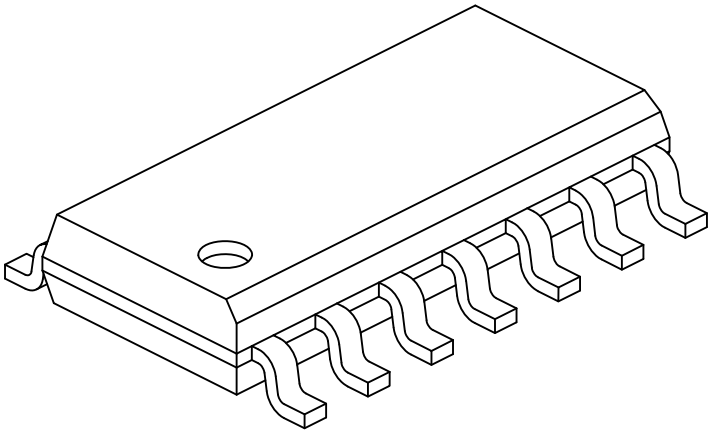


VIEW C

Microchip Technology Drawing No. C04-065-SL Rev D Sheet 1 of 2

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

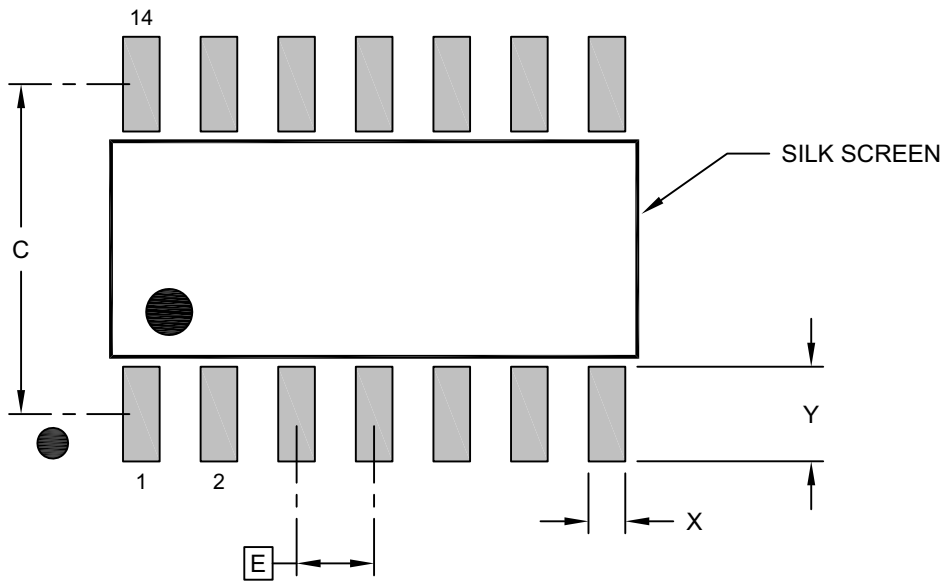
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065-SL Rev D Sheet 2 of 2

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width (X14)	X			0.60
Contact Pad Length (X14)	Y			1.55

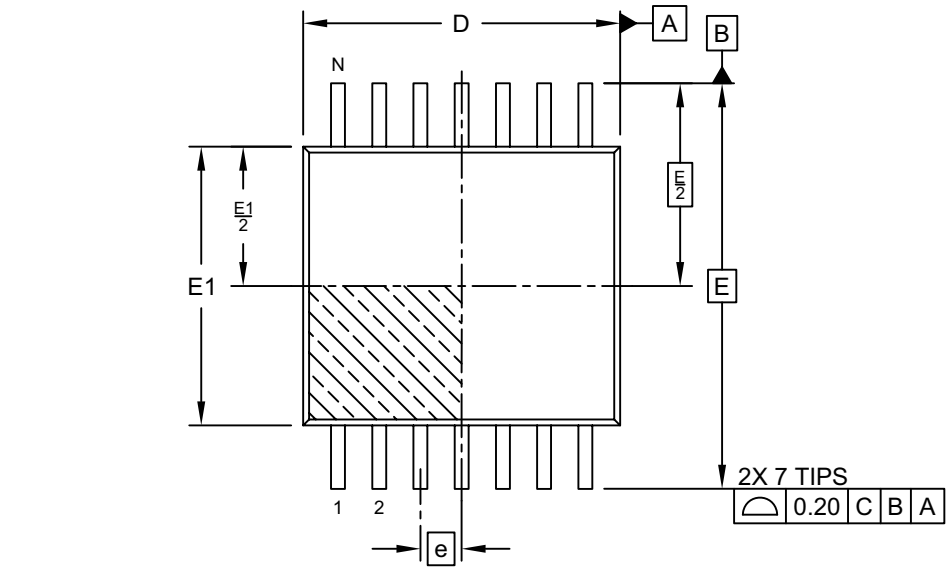
Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

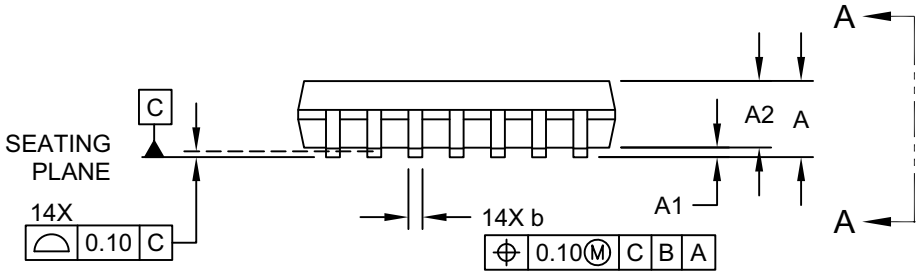
Microchip Technology Drawing No. C04-2065-SL Rev D

14-Lead Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

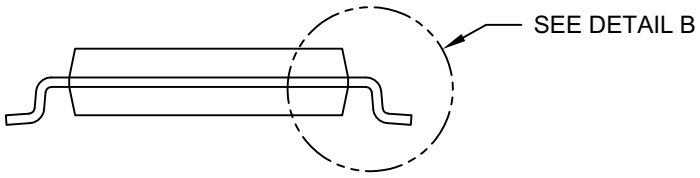
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

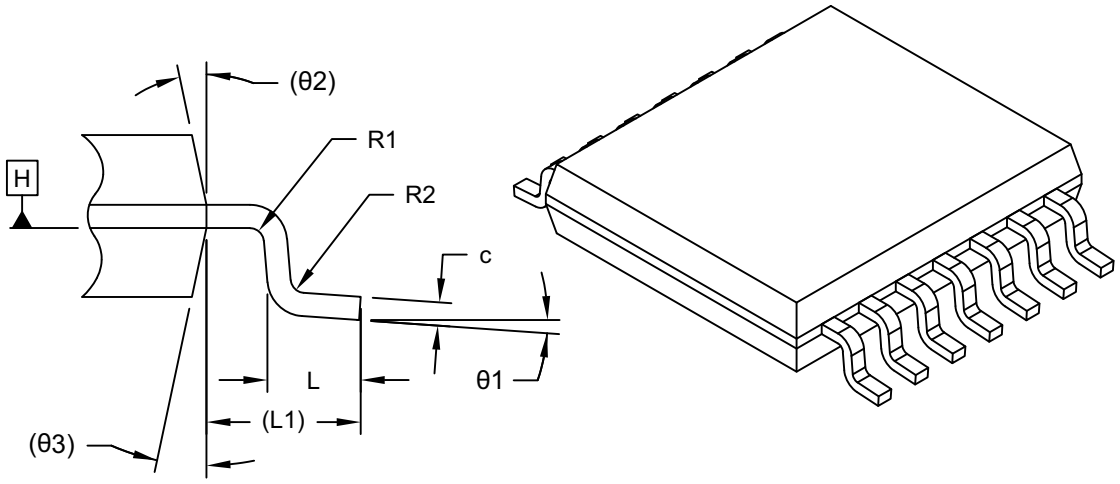


VIEW A–A

Microchip Technology Drawing C04-087 Rev E Sheet 1 of 2

14-Lead Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL B

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		14	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	1.20
Standoff	A1	0.05	–	0.15
Molded Package Thickness	A2	0.80	1.00	1.05
Overall Length	D	4.90	5.00	5.10
Overall Width	E		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Terminal Width	b	0.19	–	0.30
Terminal Thickness	c	0.09	–	0.20
Terminal Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Lead Bend Radius	R1	0.09	–	–
Lead Bend Radius	R2	0.09	–	–
Foot Angle	θ1	0°	–	8°
Mold Draft Angle	θ2	–	12° REF	–
Mold Draft Angle	θ3	–	12° REF	–

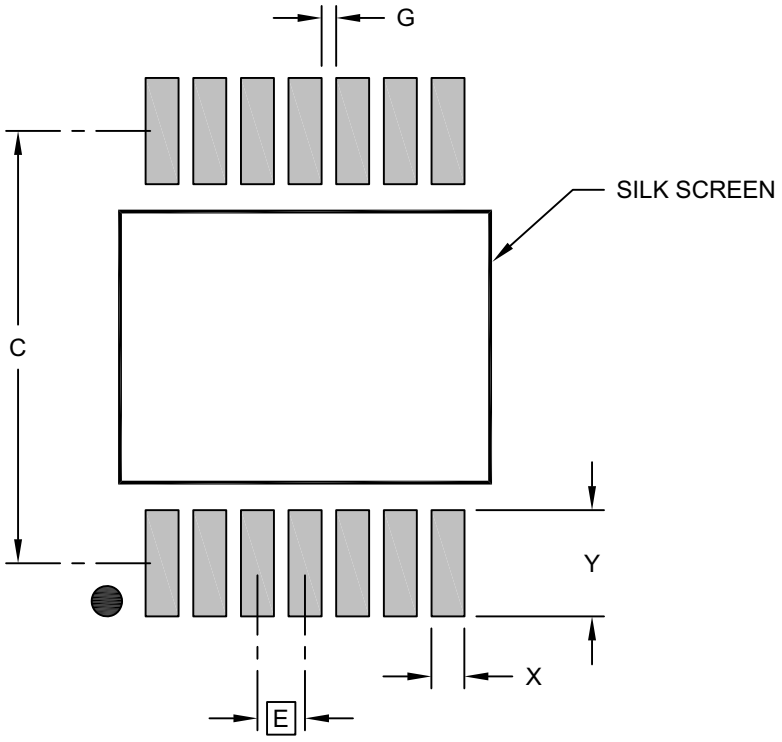
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087 Rev E Sheet 2 of 2

14-Lead Thin Shrink Small Outline Package [ST] – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		5.90	
Contact Pad Width (Xnn)	X			0.45
Contact Pad Length (Xnn)	Y			1.45
Contact Pad to Contact Pad (Xnn)	G	0.20		

Notes:

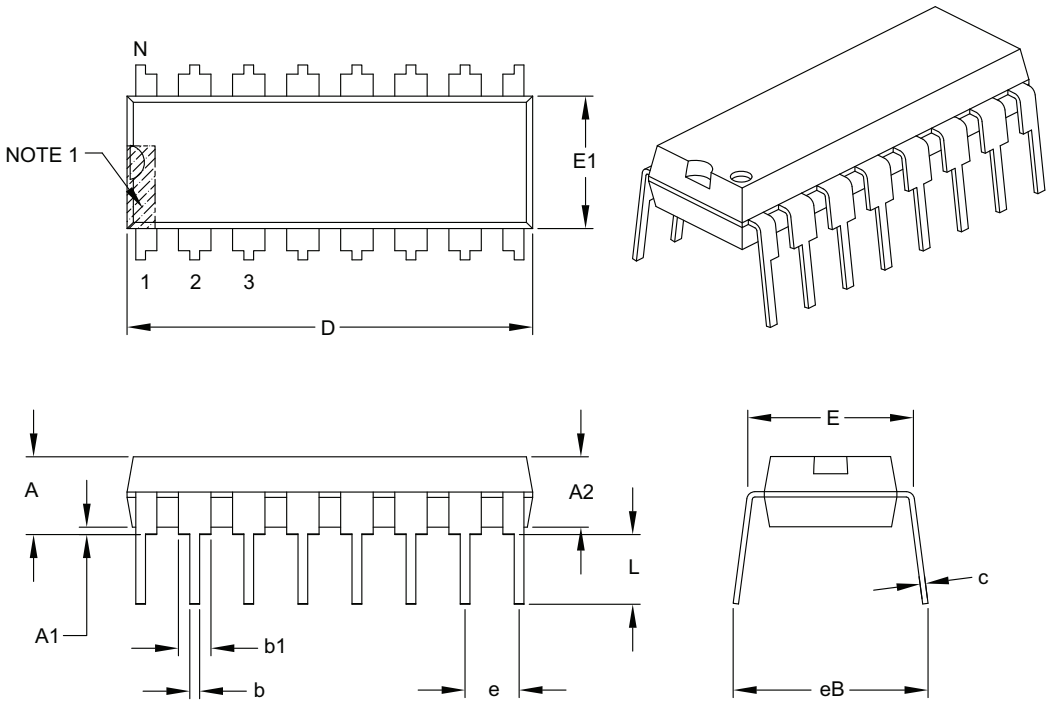
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2087 Rev E

16-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.755	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

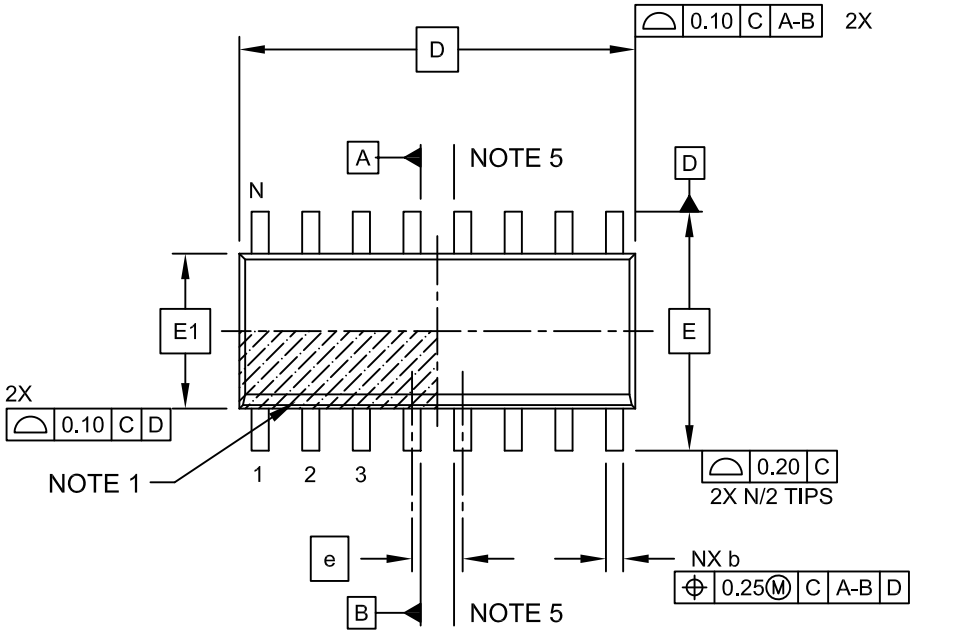
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

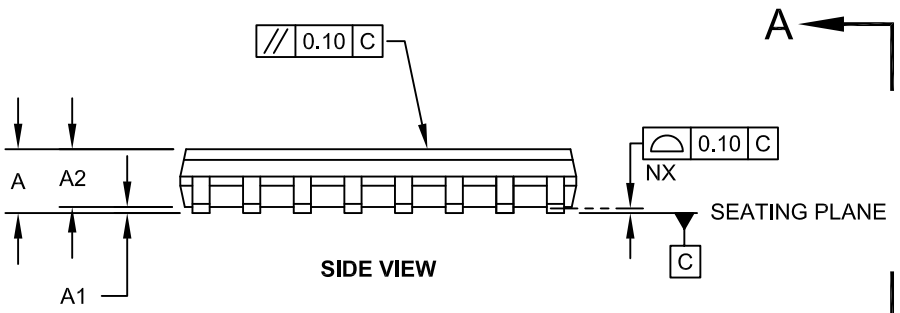
Microchip Technology Drawing C04-017B

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

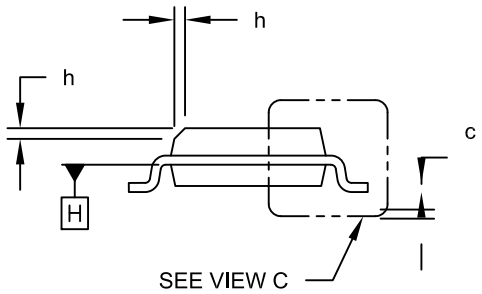
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

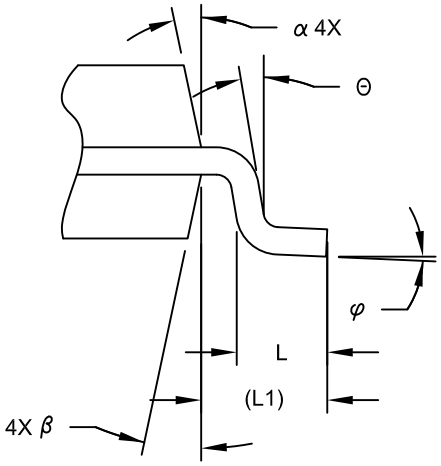


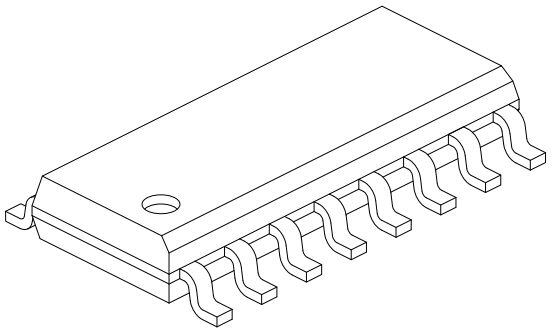
VIEW A-A

Microchip Technology Drawing No. C04-108C Sheet 1 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		9.90 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

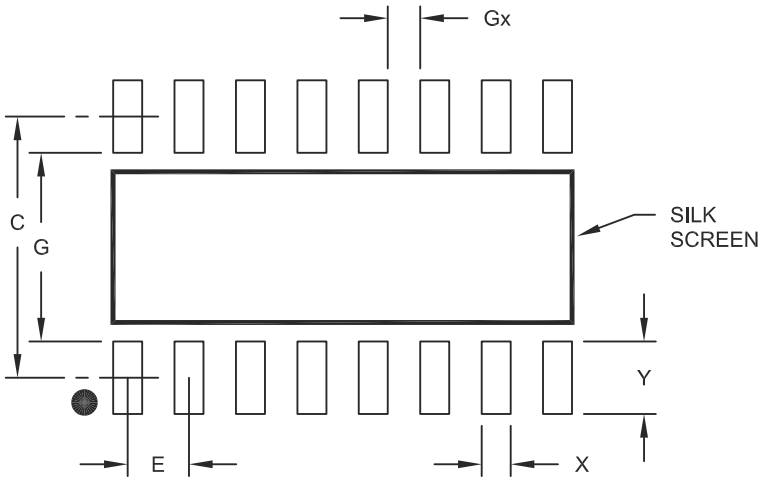
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-108C Sheet 2 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		5.40	
Contact Pad Width	X			0.60
Contact Pad Length	Y			1.50
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	3.90		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2108A

APPENDIX A: REVISION HISTORY

Revision E (October 2022)

The following is the list of modifications:

- Added AEC-Q100 qualification (does not apply to PDIP-14 and PDIP-16 packages).
- Updated Description
- Updated Package Types
- Updated Absolute Maximum Ratings †
- Updated Electrical Specifications
- Updated **Section 2.0 "Typical Performance Characteristics"**
- Added Figure 2-40 to Figure 2-43
- Updated **Section 4.0 "Device Operation"**
- Updated **Section 4.1 "Analog Inputs"**
- Updated **Section 6.2 "Maintaining Minimum Clock Speed"**
- Adds **Section 6.2.1 "Sampling Rate vs. SPI Clock Frequency"**
- Updated Product Identification System
- Updated Packaging Information

Revision D (December 2008)

The following is the list of modifications:

1. Updates to **Section 7.0 "Packaging Information"**.

Revision C (January 2007)

The following is the list of modifications:

1. Updates to the packaging diagrams.

Revision B (May 2002)

The following is the list of modifications:

1. Undocumented changes.

Revision A (February 2000)

- Initial release of this document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX
Device	Temperature Range	Package

Device	MCP3004:	4-Channel 10-Bit Serial A/D Converter
	MCP3004T:	4-Channel 10-Bit Serial A/D Converter (Tape and Reel)
	MCP3008:	8-Channel 10-Bit Serial A/D Converter
	MCP3008T:	8-Channel 10-Bit Serial A/D Converter (Tape and Reel)
Temperature Range	E =	-40°C to +125°C (Extended)
	I =	-40°C to +85°C (Industrial)
Tape and Reel Option	Blank =	Standard packaging (tube or tray)
	T =	Tape and Reel (**Note 1**)
Package	P =	Plastic DIP (300 mil Body), 14-lead, 16-lead (**Note 2**)
	SL =	Plastic SOIC (150 mil Body), 14-lead, 16-lead
	ST =	Plastic TSSOP (4.4mm), 14-lead

Examples:

a) MCP3004-I/P: Industrial Temperature, PDIP package

b) MCP3004-I/SL: Industrial Temperature, SOIC package

c) MCP3004T-E/SL: Extended Temperature, SOIC package, Tape and Reel (**Note 3**)

d) MCP3004-I/ST: Industrial Temperature, TSSOP package

e) MCP3004T-I/ST: Industrial Temperature, TSSOP package, Tape and Reel

f) MCP3004T-E/ST: Extended Temperature, TSSOP package, Tape and Reel (**Note 3**)

g) MCP3008-I/P: Industrial Temperature, PDIP package

h) MCP3008-I/SL: Industrial Temperature, SOIC package

i) MCP3008T-E/SL: Extended Temperature, SOIC package, Tape and Reel (**Note 3**).

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: PDIP package is available for industrial temperature grading only.

3: Extended Temperature part is available in Tape and Reel only.

NOTES:

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
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